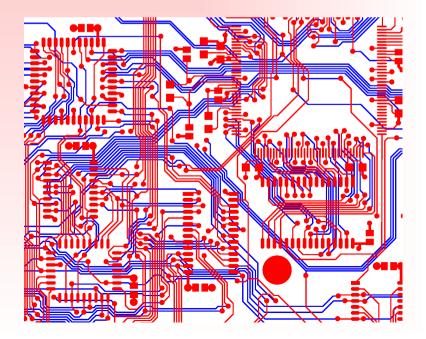
#### Seminar 32

Tutorial on Echo and Crosstalk in Printed Circuit Boards and Multi-Chip Modules — Lecture Slides

**First Edition** 

Frédéric Broydé & Evelyne Clavelier



Excem



CONSULTANTS

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## **Tutorial on Echo and Crosstalk in Printed Circuit Boards and Multi-Chip Modules — Lecture Slides**

First Edition

Frédéric Broydé & Evelyne Clavelier

Excem 12, chemin des Hauts de Clairefontaine 78580 Maule, France http://www.eurexcem.com



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#### Foreword

This tutorial explains and compares classical and innovative techniques for controlling crosstalk and echo in printed circuit assemblies and multi-chip modules.

The first part of the tutorial presents propagation models based on the theory of multiconductor transmission lines (MTLs). This theoretical part uses matrix algebra, but is not difficult to follow. It is focused on the following points which are essential for the applications considered in the second part: concisely presenting the MTL model; identifying a few common misconceptions on modal voltages and currents; comparing bi-orthonormal eigenvectors with associated eigenvectors; and explaining the total decoupling of the telegrapher's equations.

In a second part, this theoretical framework is used to describe and analyze most known techniques for reducing crosstalk and echo in a uniform multiconductor interconnection. Here, the purpose is the reduction of the number of transmission conductors and their spacing. The effect of discontinuities such as vias, connectors, etc, is not covered. The following schemes are considered: multiple single-ended links, multiple differential links, links implementing modal transmission schemes and multichannel pseudo-differential links.

Howard L. Heck Principal engineer at Intel Corporation Hillsboro, Oregon September 2011



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## 1. Introduction and definitions

 $\Box$  This tutorial is about a physical device called *interconnection*, which is used as a part of a *link* used for signal transmission. We emphasize the case where the interconnection is built in a PCB or MCM.

□ We shall use multiconductor transmission line (MTL) theory to explain and compare classical and innovative techniques for controlling crosstalk and echo.

☐ This tutorial is derived from a much more comprehensive training seminar of Excem, the Seminar 33. Many questions could not be included in the present tutorial.

□ In a first part, we present propagation models based on MTL theory. This allows us to:

- ◆ identify a few common misconceptions on modal voltages and currents;
- ◆ compare bi-orthonormal eigenvectors with associated eigenvectors;
- $\blacklozenge$  explain the total decoupling of the telegrapher's equations.



□ In a second part, this background is used to describe and analyze most known techniques for reducing crosstalk and echo in a uniform multiconductor interconnection. We will focus on innovative techniques.

□ In circuit theory, interconnections are represented using a 0-D model: the node.

☐ The transmission line (TL) model of a two-conductor interconnection may be regarded as:

- ◆ a simplified 1-D model as regard propagation along the interconnection;
- ◆ a static 2-D model for the computation of the p.u.l. parameters.

The MTL model extends the TL model to problems involving multiple conductors.

□ Why are we devoting time to the MTL model when full-wave 3-D software is available?



 $\square$  Rule A: the more comprehensive the model, the smaller the problems it can handle.

□ Rule B: optimization is useful only when a small number of dominant parameters has been identified.

□ Rule C: invention occurs only when the inventor has a simple mental image of the problem and the effect of each main parameter.

☐ The best model and problem combination is the one that gives the best result for your work type and your work time:

- ◆ for exploring innovative solution, analytical formula provide more insight;
- ◆ at the initial design stage, no detailed 3-D configuration is specified;
- ♦ for the analysis of a finalized design, the 3-D data is available (and large).



□ If we use basic circuit theory, where each interconnection is a node, our model ignores the actual behavior of interconnections: it is inaccurate at high frequencies.

 $\Box$  If we use an enhanced circuit theory where some lumped elements (e.g. a stray capacitance, or a pi network) are used to model the longer interconnections:

- ♦ our model is a little bit more accurate in the RC and LC regions;
- ◆ it may warn us of propagation problems in a design based on this model.
- □ If we use a TL model for the longer interconnections:
  - ♦ our model describes propagation and reflections;
  - ♦ it allows us to reduce echo and to compensate losses;
  - ♦ it ignores the effect of nearby conductors, which cannot be controlled.

□ If we use a MTL model for the longer interconnections:

- our model accurately describes the interactions between conductors;
- ♦ it allows us to control echo, internal crosstalk and losses.



#### □ In this tutorial:

♦ interactions between conductors within a multiconductor interconnection are treated using an MTL model;

◆ circuit models are used for other parts of the link, with caution;

◆ interactions between conductors belonging to different parallel interconnections are treated using a single MTL model;

◆ other interactions involving conductors are not considered;

♦ emission and immunity, as defined in electromagnetic compatibility (EMC), are not considered in this tutorial.

**Uniform** means invariant along the interconnection or TL or MTL.

*Homogeneous* means invariant in a cross-section of the interconnection or TL or MTL.



## 2. The 2-conductor transmission line in the frequency domain

 $\square$  We consider an interconnection with 1 transmission conductor (TC) placed close to a reference conductor (GC) used as a reference for voltage measurements.

□ Important: the GC is not necessarily a ground conductor or a combination of ground conductors.

**U** We define:

- the curvilinear abscissa z, the interconnection extending from z = 0 to z = L;
- the natural current *i* as the current flowing on the TC, toward z = L;
- $\blacklozenge$  the natural voltage *v* as the voltage between the TC and the GC.

 $\Box$  *i* and *v* are *z*-dependent.



 $\Box$  Except when otherwise stated, we shall consider frequency domain quantities and  $\sqrt{}$  is always used to denote the principal root.

□ We assume that the interconnection can be modeled as a TL. The TL model uses:

 $\blacklozenge$  a p.u.l. impedance Z' and a p.u.l. admittance Y';

◆ the telegrapher's equations

$$\begin{aligned} \frac{dv}{dz} &= -Z'i \\ \frac{di}{dz} &= -Y'v \end{aligned}$$
(1)

 $\Box$  Z' and Y' are frequency-dependent. Z' and Y' must each represent passive linear systems. Thus, their real part is nonnegative.

**The** TL is lossless if and only if  $Z' = j\omega L'$  and  $Y' = j\omega C'$  where L' and C' are real. In this case, L' and C' must be frequency independent.



 $\Box$  The TL is said to be uniform if Z' and Y' are independent of z.

□ Assuming a uniform TL, we can derive two second order differential equations

$$\begin{cases} \frac{d^2 v}{dz^2} - Y'Z' v = 0\\ \frac{d^2 i}{dz^2} - Y'Z' i = 0 \end{cases}$$
(2)

 $\Box$  The general solution of (2) can be written

$$\begin{cases} v = v_{0+} e^{-z\gamma} + v_{0-} e^{z\gamma} \\ i = i_{0+} e^{-z\gamma} + i_{0-} e^{z\gamma} \end{cases}$$
(3)

where  $v_{0+}$ ,  $v_{0-}$ ,  $i_{0+}$  and  $i_{0-}$  are *z*-independent vectors determined by the boundary conditions at z = 0 and z = L and where the propagation constant  $\gamma$  is given by:

$$\gamma = \sqrt{Y'Z'} \tag{4}$$

 $\Box v_{0+} e^{-\gamma z}$  and  $i_{0+} e^{-\gamma z}$  propagate with the propagation constant  $\gamma$  toward the far-end;  $v_{0-} e^{\gamma z}$  and  $i_{0-} e^{\gamma z}$  propagate with the propagation constant  $-\gamma$  toward the near-end.

 $\begin{cases} v_{0+} = Z_C i_{0+} \\ v_0 = -Z_C i_0 \end{cases}$ 

 $\Box$  The characteristic impedance  $Z_C$  is defined by

$$Z_C = \sqrt{\frac{Z'}{Y'}} \tag{5}$$

and it is such that

□ We define

- the voltage traveling toward the far-end, given by  $v_+ = v_{0+} e^{-\gamma z}$ ;
- the voltage traveling toward the near-end, given by  $v_{-} = v_{0-} e^{\gamma z}$ ;
- the current traveling toward the far-end, given by  $i_+ = i_{0+} e^{-\gamma z}$ ;
- the current traveling toward the near-end, given by  $i_{-} = i_{0-} e^{\gamma z}$ .



(6)



$$\Box \text{ We have } \begin{cases} v = v_{+} + v_{-} \\ i = i_{+} + i_{-} \end{cases} \begin{cases} v_{+} = Z_{C} i_{+} \\ v_{-} = -Z_{C} i_{-} \end{cases}$$
(7)

and, consequently

$$v_{+} = \frac{v + Z_{C} i}{2}$$
  $v_{-} = \frac{v - Z_{C} i}{2}$  (8)

 $\Box$  For a lossless TL,  $Z' = j\omega L'$  and  $Y' = j\omega C'$  where L' and C' are real. Thus,

$$\gamma = j\omega \sqrt{L'C'} \qquad \qquad Z_C = \sqrt{\frac{L'}{C'}} \qquad \qquad (9)$$

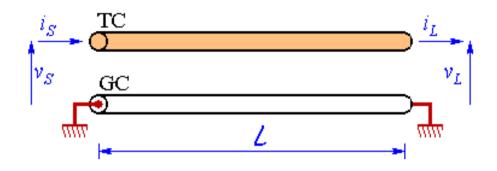
so that  $c = 1/\sqrt{L'C'}$  is the propagation velocity in the TL. The travel time is  $\tau = \frac{L}{c}$ .

□ For a lossless TL in an homogeneous dielectric, we also have

$$L'C' = \frac{\varepsilon_r}{c_0^2} = \frac{1}{c^2}$$
(10)

where  $\varepsilon_r$  is the relative permittivity of the dielectric.





 $\Box$  A scattering matrix of the interconnection, denoted by S(L) and defined by

$$\begin{pmatrix} v_S - Z_C i_S \\ v_L + Z_C i_L \end{pmatrix} = \mathcal{S}(\mathcal{L}) \begin{pmatrix} v_S + Z_C i_S \\ v_L - Z_C i_L \end{pmatrix}$$
(11)

is given by

$$S(\mathcal{L}) = e^{-\gamma \mathcal{L}} \begin{pmatrix} 0 & 1 \\ 1 & 0 \end{pmatrix}$$
(12)

*Proof.* This is a direct consequence of (3) and (8).

 $\Box S(L)$  is a usual scattering matrix only when  $Z_C$  is real.



## 3. Problems involving a TL and linear terminations

 $\Box$  At the near-end, in the configuration shown, we have

$$\begin{cases} v_{S} = e_{S} - Z_{S}i_{S} \\ v_{S} = v_{+} + v_{-} \\ i_{S} = \frac{v_{+} - v_{-}}{Z_{C}} \end{cases}$$
(13)  
$$Z_{S} \downarrow \downarrow v_{S} \downarrow v_{S} \downarrow \downarrow$$

we obtain

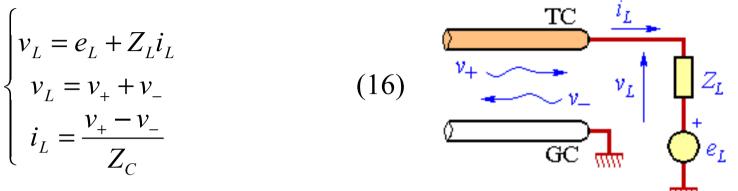
$$v_{+} = \frac{Z_{C}}{Z_{S} + Z_{C}} e_{S} + \rho_{S} v_{-} = \frac{1 - \rho_{S}}{2} e_{S} + \rho_{S} v_{-}$$
(14)

where, in this configuration, the voltage reflection coefficient is defined by

$$\rho_s = \frac{Z_s - Z_c}{Z_s + Z_c} \tag{15}$$



#### $\Box$ At the far-end, in the configuration shown, we have



we obtain

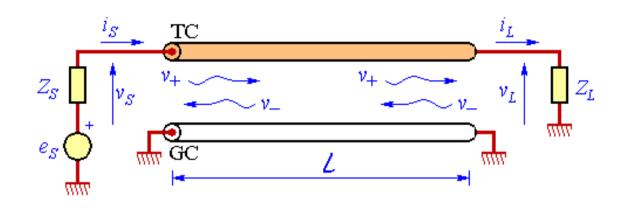
$$v_{-} = \frac{Z_{C}}{Z_{L} + Z_{C}} e_{L} + \rho_{L} v_{+} = \frac{1 - \rho_{L}}{2} e_{L} + \rho_{L} v_{+}$$
(17)

where, in this configuration, the voltage reflection coefficient is defined by

$$\rho_L = \frac{Z_L - Z_C}{Z_L + Z_C} \tag{18}$$

□ It is also possible to define current reflection coefficients.

□ A termination is matched when it produces no reflection, i.e. for  $Z_S = Z_C$  or  $Z_L = Z_C$  (we are referring to reflectionless matching, as opposed to conjugate matching).





 $\Box$  Three possible approaches to find  $v_S$  and  $v_L$  in the configuration shown above:

- using the boundary conditions to find  $v_{0+}$ ,  $v_{0-}$ ,  $i_{0+}$  and  $i_{0-}$  in (3);
- $\blacklozenge$  using the scattering matrix defined by (12) and the reflection coefficients;
- using the chain matrix (not studied in this tutorial).

□ Following the second approach, we consider multiple reflections occurring at the near-end and at the far-end, and multiple propagation through the TL. We get:

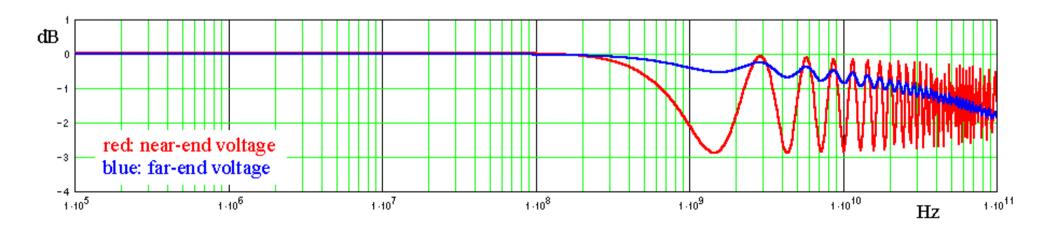
$$\begin{cases} v_{+}(0) = e_{S} \frac{Z_{C}}{Z_{S} + Z_{C}} \sum_{p=0}^{\infty} (\rho_{L} \rho_{S} e^{-2\gamma L})^{p} \\ v_{+}(L) = e_{S} \frac{Z_{C} e^{-\gamma L}}{Z_{S} + Z_{C}} \sum_{p=0}^{\infty} (\rho_{L} \rho_{S} e^{-2\gamma L})^{p} \end{cases} \text{ and } \begin{cases} v_{S} = v_{+}(0) [1 + \rho_{L} e^{-2\gamma L}] \\ v_{L} = v_{+}(L) [1 + \rho_{L}] \end{cases}$$
(19)



Thus, we obtain

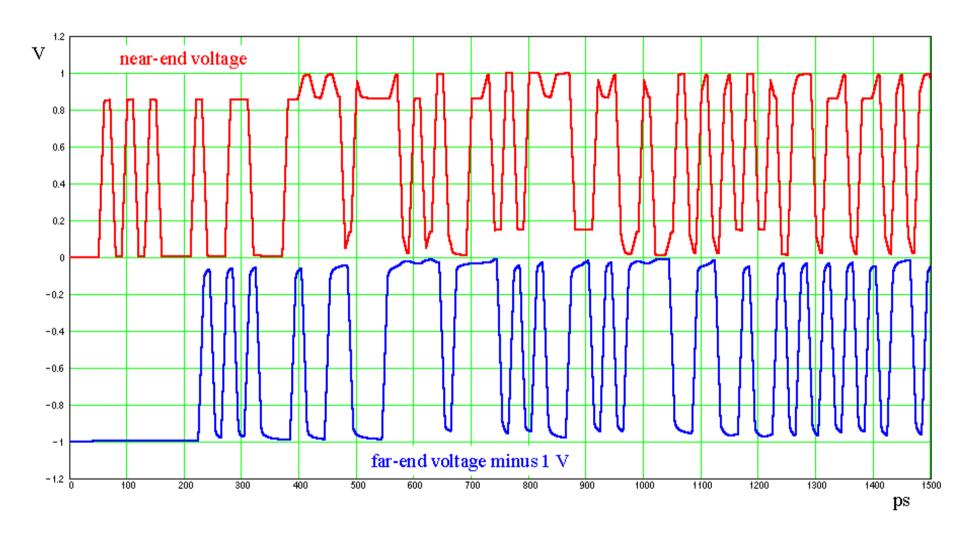
$$\begin{cases} v_{S} = \frac{e_{S}Z_{C}}{Z_{S} + Z_{C}} \frac{1 + \rho_{L} e^{-2\gamma L}}{1 - \rho_{L} \rho_{S} e^{-2\gamma L}} \\ v_{L} = \frac{e_{S}Z_{C} e^{-\gamma L}}{Z_{S} + Z_{C}} \frac{1 + \rho_{L}}{1 - \rho_{L} \rho_{S} e^{-2\gamma L}} \end{cases}$$
(20)

☐ An example involving a 20-mm long microstrip built on AsGa, having resistive losses and negligible dielectric losses:



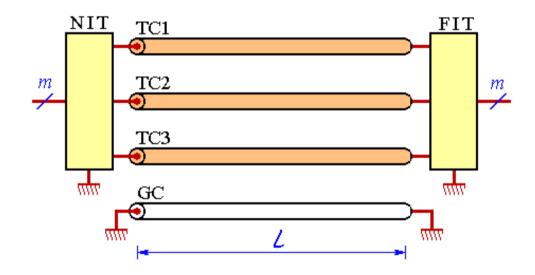


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## 4. Telegrapher's equations of a uniform MTL and modal decomposition



 $\square$  We consider a link providing *m* channels comprising:

- an interconnection having *n* TCs and a GC, where  $n \ge m$ ;
- ◆ a near-end interface and termination device (NIT);
- ◆ a far-end interface and termination device (FIT).



□ The GC is used as a reference for voltage measurements.

□ Important: the GC is not necessarily a ground conductor or a combination of ground conductors.

□ We number the TCs from 1 to *n*, and we define:

- the curvilinear abscissa z, the interconnection extending from z = 0 to z = L;
- the natural current  $i_j$  as the current flowing on the TC *j*, toward z = L;
- the natural voltage  $v_j$  as the voltage between the TC *j* and the GC;
- the column-vector **i** of the natural currents  $i_1, ..., i_n$ , which depends on *z*;
- the column-vector **v** of the natural voltages  $v_1, ..., v_n$ , which depends on z.

□ Except when otherwise stated, we shall consider frequency domain quantities.



 $\square$  We assume that the interconnection can be modeled as a MTL. The (n + 1)-conductor MTL model uses [1]:

- $\blacklozenge$  a p.u.l. impedance matrix Z' and a p.u.l. admittance matrix Y';
- $\blacklozenge$  the telegrapher's equations

$$\frac{d \mathbf{v}}{dz} = -\mathbf{Z'}\mathbf{i}$$

$$\frac{d \mathbf{i}}{dz} = -\mathbf{Y'}\mathbf{v}$$
(21)

 $\Box$  Z' and Y' are frequency-dependent symmetric matrices of size  $n \times n$ . Z' and Y' must each represent a passive linear system. Thus, their real part is positive semidefinite [8, § 7.1]. We shall assume that Z' and Y' are invertible.

**The MTL is lossless if and only if**  $\mathbf{Z}' = j\omega \mathbf{L}'$  and  $\mathbf{Y}' = j\omega \mathbf{C}'$  where  $\mathbf{L}'$  and  $\mathbf{C}'$  are real matrices of size  $n \times n$ . In this case,  $\mathbf{L}'$  and  $\mathbf{C}'$  must be frequency independent.



 $\Box$  The MTL is said to be uniform if **Z**' and **Y**' are independent of *z*.

□ Assuming a uniform MTL, we can derive two second order differential equations

$$\begin{cases} \frac{d^{2}\mathbf{v}}{dz^{2}} - \mathbf{Z'Y'}\mathbf{v} = \mathbf{0} \\ \frac{d^{2}\mathbf{i}}{dz^{2}} - \mathbf{Y'Z'}\mathbf{i} = \mathbf{0} \end{cases}$$
(22)

 $\Box$  Z'Y' and Y'Z' are similar [8, § 1.3.20]. We shall assume that Z'Y' is diagonalizable. In this case, there exists two invertible matrices T and S such that:

$$\begin{cases} \mathbf{T}^{-1}\mathbf{Y'Z'T} = \Gamma^2 \\ \mathbf{S}^{-1}\mathbf{Z'Y'S} = \Gamma^2 \end{cases} \text{ where } \Gamma = \operatorname{diag}_n(\gamma_1, \dots, \gamma_n) \tag{23}$$

is the diagonal matrix of order *n* of the propagation constants  $\gamma_i$ , chosen with an argument  $\psi \in \left[-\pi/2, \pi/2\right]$ , so that the  $\gamma_i$  are principal square roots.



**T** and **S** define a *modal transform* for the natural currents and the natural voltages. We define  $\mathbf{v}_M$  and  $\mathbf{i}_M$  by

$$\mathbf{v} = \mathbf{S} \mathbf{v}_{M}$$
  
$$\mathbf{i} = \mathbf{T} \mathbf{i}_{M}$$
 (24)

where

- we use  $\mathbf{i}_M$  to denote the vector of the *n* modal currents  $i_{M1}, ..., i_{Mn}$ ;
- we use  $\mathbf{v}_M$  to denote the vector of the *n* modal voltages  $v_{M1}, ..., v_{Mn}$ ;
- we call **S** the *transition matrix from modal voltages to natural voltages*;
- we call **T** the *transition matrix from modal currents to natural currents*.

 $\Box$  Using (23) and (24), (22) takes on a form which contains *n* times (2):

$$\begin{cases} \frac{d^2 \mathbf{v}_M}{dz^2} - \Gamma^2 \mathbf{v}_M = \mathbf{0} \\ \frac{d^2 \mathbf{i}_M}{dz^2} - \Gamma^2 \mathbf{i}_M = \mathbf{0} \end{cases}$$
(25)



 $\Box$  The general solution of (25) is

$$\begin{cases} \mathbf{v}_{M} = e^{-z\Gamma} \, \mathbf{v}_{M0+} + e^{z\Gamma} \, \mathbf{v}_{M0-} \\ \mathbf{i}_{M} = e^{-z\Gamma} \, \mathbf{i}_{M0+} + e^{z\Gamma} \, \mathbf{i}_{M0-} \end{cases}$$
(26)

where  $\mathbf{v}_{M0+}$ ,  $\mathbf{v}_{M0-}$ ,  $\mathbf{i}_{M0+}$  and  $\mathbf{i}_{M0-}$  are *z*-independent vectors depending on the boundary conditions at z = 0 and  $z = \mathcal{L}$ .

□ For a function f(u) of the variable  $u \in \mathbb{C}$  and a diagonal matrix diag<sub>n</sub> $(a_1,...,a_n)$ , we define  $f(\text{diag}_n(a_1,...,a_n)) = \text{diag}_n(f(a_1),...,f(a_n))$ . This was used in (26).

□ For any  $\alpha \in \{1, ..., n\}$ , a modal current  $i_{M\alpha}$  and a modal voltage  $v_{M\alpha}$  may propagate with the propagation constant  $\gamma_{\alpha}$  toward the far-end, or with the opposite propagation constant  $-\gamma_{\alpha}$  toward the near-end.

□ The column-vectors of S (respectively, of T) are defined as linearly independent eigenvectors of Z'Y' (respectively, of Y'Z'). Consequently, S and T are not uniquely defined by (23).

# EXCEM

## 5. The characteristic impedance matrix

 $\Box$  For a wave traveling toward the far-end, the column-vector of the modal voltages is  $\mathbf{v}_{M+} = e^{-z\Gamma} \mathbf{v}_{M0+}$  and the column-vector of the modal currents is  $\mathbf{i}_{M+} = e^{-z\Gamma} \mathbf{i}_{M0+}$ .

 $\Box$  The modal characteristic impedance matrix  $\mathbf{Z}_{MC}$  is defined by

$$\mathbf{v}_{M+} = \mathbf{Z}_{MC} \,\mathbf{i}_{M+} \tag{27}$$

and given by

$$\mathbf{Z}_{MC} = \Gamma^{-1} \mathbf{S}^{-1} \mathbf{Z}' \mathbf{T} = \Gamma \mathbf{S}^{-1} \mathbf{Y}'^{-1} \mathbf{T} = \mathbf{S}^{-1} \mathbf{Y}'^{-1} \mathbf{T} \Gamma = \mathbf{S}^{-1} \mathbf{Z}' \mathbf{T} \Gamma^{-1}$$
(28)

 $\Box$  For a wave traveling toward the near-end, the column-vector of the modal voltages is  $\mathbf{v}_{M-} = e^{z\Gamma} \mathbf{v}_{M0-}$  and the column-vector of the modal currents is  $\mathbf{i}_{M-} = e^{z\Gamma} \mathbf{i}_{M0-}$ , so that

$$\mathbf{v}_{M-} = -\mathbf{Z}_{MC} \,\mathbf{i}_{M-} \tag{29}$$

 $\Box$  The modal characteristic impedance matrix depends on the choice of S and T.

 $\square$  We can now define the characteristic impedance matrix  $\mathbb{Z}_C$  of the multiconductor transmission line, as:

$$\mathbf{Z}_{C} = \mathbf{S} \, \mathbf{Z}_{MC} \mathbf{T}^{-1} \tag{30}$$

 $\Box$  Using (28), we get

$$\mathbf{Z}_{C} = \mathbf{S} \, \boldsymbol{\Gamma}^{-1} \, \mathbf{S}^{-1} \mathbf{Z'} = \mathbf{S} \, \boldsymbol{\Gamma} \, \mathbf{S}^{-1} \mathbf{Y'}^{-1} = \mathbf{Y'}^{-1} \mathbf{T} \boldsymbol{\Gamma} \mathbf{T}^{-1} = \mathbf{Z'} \, \mathbf{T} \boldsymbol{\Gamma}^{-1} \mathbf{T}^{-1}$$
(31)

 $\Box$  For a wave traveling toward the far-end, the column-vector of the natural voltages is  $\mathbf{v}_{+} = \mathbf{S} \, \mathbf{v}_{M+} = \mathbf{S} \, e^{-z\Gamma} \, \mathbf{v}_{M0+}$  and the column-vector of the modal currents is  $\mathbf{i}_{+} = \mathbf{T} \, \mathbf{i}_{M+} = \mathbf{T} \, e^{-z\Gamma} \, \mathbf{i}_{M0+}$ . We find:

$$\mathbf{v}_{+} = \mathbf{Z}_{C} \,\mathbf{i}_{+} \tag{32}$$



 $\Box$  For a wave traveling toward the near-end, the column-vector of the natural voltages is  $\mathbf{v}_{-} = \mathbf{S} \mathbf{v}_{M-} = \mathbf{S} e^{z\Gamma} \mathbf{v}_{M0-}$  and the column-vector of the modal currents is  $\mathbf{i}_{-} = \mathbf{T} \mathbf{i}_{M-} = \mathbf{T} e^{z\Gamma} \mathbf{i}_{M0-}$ . We find:

$$\mathbf{v}_{-} = -\mathbf{Z}_{C} \,\mathbf{i}_{-} \tag{33}$$

 $\Box$  Since (32) or (33) hold for any value  $\mathbf{i}_+$ , each can be used as a definition of  $\mathbf{Z}_C$ . Thus,  $\mathbf{Z}_C$  is unique and does not depend on the choice of the matrices **S** and **T**.

 $\Box$  For a lossless MTL, real and frequency-independent **T** and **S** can be computed [4], and we have

$$\gamma_{\alpha} = \frac{j\omega}{c_{\alpha}} \tag{34}$$

where the positive real  $c_{\alpha}$  is the propagation velocity of the mode  $\alpha$ . Thus,  $\mathbb{Z}_{C}$  is real. The minimum travel time is  $\tau_{\min} = \frac{\mathcal{L}}{\max(c_{\alpha})}$ .

(36)

□ Special case of a lossless MTL where the electric field sees an homogeneous dielectric (e.g., a multiconductor stripline operated in the LC and skin effect regions):

• we may consider that we have a lossless MTL having an homogeneous dielectric of permittivity  $\varepsilon_r$ , for which it can be shown that [1] [88],

 $\mathbf{Z'Y'} = \mathbf{Y'Z'} = -\omega^2 \varepsilon_r \varepsilon_0 \mu_0 \mathbf{1}_n$ 

$$\mathbf{C'} = \varepsilon_r \varepsilon_0 \mu_0 \mathbf{L'}^{-1} \tag{35}$$

so that

• we can use 
$$\mathbf{S} = \mathbf{T} = \mathbf{1}_n$$
 so that

$$\Gamma = \frac{j\omega}{c_0 / \sqrt{\varepsilon_r}} \mathbf{1}_n \qquad \mathbf{Z}_C = \frac{\mathbf{C'}^{-1}}{c_0 / \sqrt{\varepsilon_r}} = \frac{c_0}{\sqrt{\varepsilon_r}} \mathbf{L'} \qquad (37)$$

There is only one propagation constant: we have a completely degenerate MTL.





# 6. Biorthonormal eigenvectors and associated eigenvectors

 $\Box$  Z' and Y' being symmetric, if a diagonalization of the matrix Y'Z' produces a matrix T satisfying the first line of (23), i.e.  $\mathbf{T}^{-1}\mathbf{Y'Z'T} = \Gamma^2$ , we find that a solution of the second line of (23), i.e.  $\mathbf{S}^{-1}\mathbf{Z'Y'S} = \Gamma^2$  is

$$\mathbf{S} = {}^{t} \mathbf{T}^{-1} \tag{38}$$

where  ${}^{t}A$  is used to denote the transpose of a matrix A.

 $\Box$  In other words, we can always compute the eigenvectors  $T_i$  of Y'Z' and the eigenvectors  $S_i$  of Z'Y' in such a way that they satisfy the relation

$${}^{t}\mathbf{S}_{i} \mathbf{T}_{j} = \boldsymbol{\delta}_{ij}$$
(39)

where  $\delta_{ii}$  is Kronecker's symbol. This is called the *biorthonormal property* [15].



 $\square$  The possibility of using (38) in (31) shows that  $\mathbb{Z}_C$  is symmetric.

□ Note that:

- ♦ biorthonormal eigenvectors can be used with lossy and lossless MTLs;
- (38) is not a property of (23), it is only a possible choice.

□ If a diagonalization of the matrix  $\mathbf{Y}'\mathbf{Z}'$  produces a matrix  $\mathbf{T}$  satisfying the first line of (23), i.e.  $\mathbf{T}^{-1}\mathbf{Y}'\mathbf{Z}'\mathbf{T} = \Gamma^2$ , we find that a solution of the second line of (23), i.e.  $\mathbf{S}^{-1}\mathbf{Z}'\mathbf{Y}'\mathbf{S} = \Gamma^2$  is

$$\mathbf{S} = j\boldsymbol{\omega} c_K \mathbf{Y'}^{-1} \mathbf{T}$$
(40)

where  $c_K$  is an arbitrary scalar different from zero, which may depend on frequency, and which has the dimensions of a p.u.l. capacitance.

 $\Box$  When **S** and **T** are defined by (23) and (40), we say that they are *associated*, and that the eigenvectors contained in **S** and **T** (i.e. their column-vectors) are associated [10] [12] [16] [22] [27] [37] [38].



 $\Box$  Using (21) and (24), we can write

$$\begin{cases} \frac{d \mathbf{v}_{M}}{dz} = -\mathbf{Z}'_{M} \mathbf{i}_{M} \\ \frac{d \mathbf{i}_{M}}{dz} = -\mathbf{Y}'_{M} \mathbf{v}_{M} \end{cases} \quad \text{where} \quad \begin{cases} \mathbf{Z}'_{M} = \mathbf{S}^{-1} \mathbf{Z}' \mathbf{T} \\ \mathbf{Y}'_{M} = \mathbf{T}^{-1} \mathbf{Y}' \mathbf{S} \end{cases}$$
(41)

This defines the modal p.u.l. impedance matrix  $\mathbf{Z'}_M$  and the modal p.u.l. admittance matrix  $\mathbf{Y'}_M$ . For associated eigenvectors, we find

$$\mathbf{Z}'_{M} = \left(j\omega c_{K} \mathbf{Y'}^{-1}\mathbf{T}\right)^{-1} \mathbf{Z'T} = \frac{1}{j\omega c_{K}} \mathbf{T}^{-1} \mathbf{Y'Z'T} = \frac{\Gamma^{2}}{j\omega c_{K}}$$
(42)

and

$$\mathbf{Y}'_{M} = \mathbf{T}^{-1} \mathbf{Y}' \left( j \boldsymbol{\omega} \, c_{K} \, \mathbf{Y}'^{-1} \, \mathbf{T} \right) = j \boldsymbol{\omega} \, c_{K} \, \mathbf{1}_{n} \tag{43}$$

Thus, we have shown that, for associated eigenvectors:

• the modal p.u.l. impedance matrix  $\mathbf{Z}'_{M} = \mathbf{\tilde{S}}^{-1}\mathbf{Z'T}$  is diagonal; and • the modal p.u.l. admittance matrix  $\mathbf{Y}'_{M} = \mathbf{T}^{-1}\mathbf{Y'S}$  is diagonal.



 $\Box$  For associated eigenvectors, the modal characteristic impedance matrix is diagonal and given by 1

$$\mathbf{Z}_{MC} = \frac{1}{j\omega \ c_K} \ \Gamma \tag{44}$$

□ A more general possible choice (generalized associated eigenvectors) is given by

$$\mathbf{S} = j\boldsymbol{\omega} \ \mathbf{Y'}^{-1} \, \mathbf{T} \, \mathbf{c}_K \tag{45}$$

where  $\mathbf{c}_K$  is an arbitrary invertible diagonal matrix, possibly frequency-dependent, and having the dimensions of a p.u.l. capacitance.

#### □ We find that, for generalized associated eigenvectors:

- the modal p.u.l. impedance matrix  $\mathbf{Z}'_{M} = \mathbf{S}^{-1}\mathbf{Z}'\mathbf{T}$  is diagonal;
- the modal p.u.l. admittance matrix  $\mathbf{Y}'_{M} = \mathbf{T}^{-1}\mathbf{Y}'\mathbf{S}$  is diagonal;
- ◆ the modal characteristic impedance matrix is diagonal and its value is

$$\mathbf{Z}_{MC} = \frac{1}{j\omega} \mathbf{c}_{K}^{-1} \Gamma$$
(46)



### 7. The choice of eigenvectors and total decoupling

 $\square$  For associated eigenvectors, for a wave propagating in a given direction and for any  $\alpha \in \{1, ..., n\}$ , by (27), (29) and (44) we have:

$$v_{M\alpha} = \frac{\varepsilon_D}{j\omega \ c_K} \ \gamma_\alpha \ i_{M\alpha} \tag{47}$$

where  $\varepsilon_D$  is equal to 1 if the wave propagates toward the far-end, or to -1 if the wave propagates toward the near-end.

 $\Box$  For generalized associated eigenvectors, instead of (47), using (27), (29) and (46), we find:

$$v_{M\alpha} = \frac{\varepsilon_D}{j\omega \ c_{K\alpha\alpha}} \ \gamma_\alpha \ i_{M\alpha} \tag{48}$$

where  $c_{K\alpha\beta}$  denotes an entry of  $\mathbf{c}_{K}$ .



 $\Box$  According to (26) and to (47) or (48), the propagation of  $v_{M\alpha}$  and  $i_{M\alpha}$  can be viewed as the propagation on a ficticious 2-conductor transmission line having the propagation constant  $\gamma_{\alpha}$  and the characteristic impedance  $\gamma_{\alpha} / j\omega c_{K}$ .

 $\square$  We see that the diagonalization of  $\mathbf{Y'Z'}$  and  $\mathbf{Z'Y'}$  in (23) provides a decoupling in (26), but it need not provide total decoupling.

 $\Box$  We say that a *total decoupling* occurs when a particular choice of **T** and **S** leads to (47) or (48) so that an equivalent circuit comprising *n* independent 2-conductor TLs may be defined for the (*n* + 1) conductor MTL.

**Theorem**: Total decoupling means that  $\mathbf{Z}_{MC}$  is diagonal. It only occurs for generalized associated eigenvectors, i.e. eigenvectors complying with (45).

*Proof.* The  $c_{K\alpha\alpha}$  being arbitrary scalars, (48) means that  $\mathbf{Z}_{MC}$  is diagonal. By (28), we have  $\mathbf{S} = \mathbf{Y'}^{-1} \mathbf{T} \Gamma \mathbf{Z}_{MC}^{-1}$  which complies with (45) for  $j \boldsymbol{\omega} \mathbf{c}_{K} = \Gamma \mathbf{Z}_{MC}^{-1}$ .



□ In the literature, we find that:

♦ **T** and **S** satisfy  $\mathbf{S} = {}^{t}\mathbf{T}^{-1}$  [7] [14, § 4.3.2] [17, § 6.2.6] [80, § 4.4.1];

♦ the modes are orthogonal, i.e. the eigen-voltages (the columns of S) or the eigen-currents (the columns of T) are orthogonal [9] [13, col. 1] [19, col. 4] [32] [33] [80, § 4.4] [85] [86];

• the modal impedance matrix  $\mathbf{Z}'_{M} = \mathbf{S}^{-1}\mathbf{Z}'\mathbf{T}$  and/or the modal admittance matrix  $\mathbf{Y}'_{M} = \mathbf{T}^{-1}\mathbf{Y}'\mathbf{S}$  are diagonal [6] [7] [80, § 4.4.1];

♦ the 3 assertions above need not be correct [15] [37, § X] [38, § V and § VI].

 $\square$  Bi-orthonormal eigenvectors, defined by the relation  $\mathbf{S} = {}^{t} \mathbf{T}^{-1}$  are such that total decoupling need not be present, so that it need not lead us to an equivalent circuit based on *n* uncoupled 2-conductor transmission lines.

 $\Box$  However, when all  $\gamma_{\alpha}$  are different from one another, i.e. when there is no degenerate propagation constants, any choice of **T** and **S** complies with (45), so that bi-orthonormal eigenvectors provide a total decoupling in this case.



 $\Box$  However, in the case of a lossless MTL, it is possible to compute a matrix T such that [4] [5] [14, § 4.4.3]

$$\mathbf{T}^{-1} = {}^{t}\mathbf{T} \mathbf{C}'^{-1} \tag{49}$$

for which bi-orthogonal eigenvectors comply with (45), so that they provide a total decoupling (at the cost of a complex algorithm).

Using (generalized) associated eigenvectors, because of total decoupling:

• any (n + 1)-conductor MTL has an equivalent circuit comprising voltagecontrolled voltage sources, current-controlled current sources and *n* uncoupled 2-conductor transmission lines;

♦ in general, all electrical parameters of the equivalent circuit are complex and frequency-dependent;

♦ if the MTL is lossless, all electrical parameters of the equivalent circuit are real and frequency-independent. It can be used in SPICE [10] [12] [16].



□ Example A: This example relates to a multiconductor microstrip interconnection having 8 TCs, built on a polyimide substrate. We neglect losses.

The worksheet of Annex A shows that, in this example:

- $\blacklozenge$  there are no degenerate eigenvalues (see § 2);
- $Z_C$  is real, not diagonal, and may be realized with a network of n (n + 1)/2 resistors, some of which being obviously superfluous (see § 3 and § 4);
- $\blacklozenge$  the eigen-voltages and the eigen-currents are not orthogonal (see § 5);
- for associated eigenvectors,  $\mathbf{Z}'_{M}$  and  $\mathbf{Y}'_{M}$  are diagonal (see § 6);
- for our choice of bi-orthonormal eigenvectors,  $\mathbf{Z}_{MC}$ ,  $\mathbf{Z}'_{M}$  and  $\mathbf{Y}'_{M}$  are diagonal (see § 7 and § 8).
- ✓ Why would the computation of T in § 2 be inadequate for degenerate eigenvalues? Answer: the function *eigenvect* cannot return independent eigenvectors for a degenerate eigenvalue.



□ Example B: This example relates to the multiconductor stripline interconnection having 8 TCs, built in a polyimide substrate. We neglect losses.

The worksheet of Annex B shows that, in this example:

 $\blacklozenge$  we assume an homogeneous dielectric, so that (35) is used to compute C' and completely degenerate eigenvalues are obtained (see § 1 and § 2);

•  $Z_C$  is real, not diagonal, and may be realized with a network of n (n + 1)/2 resistors, many of which being obviously superfluous (see § 3 and § 4);

 $\blacklozenge$  for our choice of associated eigenvectors, the eigen-voltages are not orthogonal while the eigen-currents are orthogonal (see § 5);

• for associated eigenvectors,  $\mathbf{Z}'_{M}$  and  $\mathbf{Y}'_{M}$  are diagonal (see § 6);

• for our choice of bi-orthonormal eigenvectors,  $\mathbf{Z}_{MC}$ ,  $\mathbf{Z}'_{M}$  and  $\mathbf{Y}'_{M}$  are not diagonal (see § 7 and § 8).



### 8. Propagation in the frequency domain

 $\Box$  According to (26),  $\mathbf{v}_M$  and  $\mathbf{i}_M$  are given by

$$\begin{cases} \mathbf{v}_{M} = \mathbf{v}_{M+} + \mathbf{v}_{M-} \\ \mathbf{i}_{M} = \mathbf{i}_{M+} + \mathbf{i}_{M-} \end{cases}$$
(50)

where

 $\begin{cases} \mathbf{v}_{M+} = e^{-z\Gamma} \, \mathbf{v}_{M0+} \\ \mathbf{i}_{M+} = e^{-z\Gamma} \, \mathbf{i}_{M0+} \end{cases} \quad \text{and} \quad \begin{cases} \mathbf{v}_{M-} = e^{z\Gamma} \, \mathbf{v}_{M0-} \\ \mathbf{i}_{M-} = e^{z\Gamma} \, \mathbf{i}_{M0-} \end{cases}$ (51)

where

•  $\mathbf{v}_{M^+}$  is the column-vector of the modal voltages traveling toward the far-end, •  $\mathbf{v}_{M^-}$  is the column-vector of the modal voltages traveling toward the near-end, •  $\mathbf{i}_{M^+}$  is the column-vector of the modal currents traveling toward the far-end, •  $\mathbf{i}_{M^-}$  is the column-vector of the modal currents traveling toward the near-end, •  $\mathbf{v}_{M0^+}$ ,  $\mathbf{v}_{M0^-}$ ,  $\mathbf{i}_{M0^+}$  and  $\mathbf{i}_{M0^-}$  are *z*-independent column-vectors depending on the boundary conditions at z = 0 and  $z = \mathcal{L}$ .



 $\Box$  Thus, a *modal scattering matrix*, denoted by  $S_M(z)$  and defined by

$$\begin{pmatrix} \mathbf{v}_{M-}(0) \\ \mathbf{v}_{M+}(z) \end{pmatrix} = S_M(z) \begin{pmatrix} \mathbf{v}_{M+}(0) \\ \mathbf{v}_{M-}(z) \end{pmatrix}$$
(52)

is given by

$$S_{M}(z) = \begin{pmatrix} 0 & e^{-z\Gamma} \\ e^{-z\Gamma} & 0 \end{pmatrix}$$
(53)

**D** By (27) and (29), we have

$$\mathbf{v}_{M+} = \frac{\mathbf{v}_M + \mathbf{Z}_{MC} \,\mathbf{i}_M}{2} \qquad \qquad \mathbf{v}_{M-} = \frac{\mathbf{v}_M - \mathbf{Z}_{MC} \,\mathbf{i}_M}{2} \tag{54}$$



(56)

 $\Box$  Using (50), (51),  $\mathbf{v} = \mathbf{S} \mathbf{v}_M$  and  $\mathbf{i} = \mathbf{T} \mathbf{i}_M$ , we find that  $\mathbf{v}$  and  $\mathbf{i}$  are given by

$$\begin{cases} \mathbf{v} = \mathbf{v}_{+} + \mathbf{v}_{-} \\ \mathbf{i} = \mathbf{i}_{+} + \mathbf{i}_{-} \end{cases}$$
(55)

where

where

v<sub>+</sub> is the column-vector of the natural voltages traveling toward the far-end,
v<sub>-</sub> is the column-vector of the natural voltages traveling toward the near-end,
i<sub>+</sub> is the column-vector of the natural currents traveling toward the far-end,
i<sub>-</sub> is the column-vector of the natural currents traveling toward the near-end,
v<sub>0+</sub>, v<sub>0-</sub>, i<sub>0+</sub> and i<sub>0-</sub> are *z*-independent column-vectors depending on the boundary conditions at *z* = 0 and *z* = *L*.

 $\begin{cases} \mathbf{v}_{+} = \mathbf{S} e^{-z\Gamma} \mathbf{S}^{-1} \mathbf{v}_{0+} \\ \mathbf{i}_{-} = \mathbf{T} e^{-z\Gamma} \mathbf{T}^{-1} \mathbf{i}_{0-} \end{cases} \text{ and } \begin{cases} \mathbf{v}_{-} = \mathbf{S} e^{z\Gamma} \mathbf{S}^{-1} \mathbf{v}_{0-} \\ \mathbf{i}_{-} = \mathbf{T} e^{z\Gamma} \mathbf{T}^{-1} \mathbf{i}_{0-} \end{cases}$ 

 $\Box$  v<sub>+</sub>, v<sub>-</sub>, i<sub>+</sub> and i<sub>-</sub> are independent of the choice of eigenvectors.



 $\Box$  Thus, a *scattering matrix*, denoted by S(z) and defined by

$$\begin{pmatrix} \mathbf{v}_{-}(0) \\ \mathbf{v}_{+}(z) \end{pmatrix} = S(z) \begin{pmatrix} \mathbf{v}_{+}(0) \\ \mathbf{v}_{-}(z) \end{pmatrix}$$
(57)

is given by

$$S(z) = \begin{pmatrix} 0 & \mathbf{S}e^{-z\Gamma}\mathbf{S}^{-1} \\ \mathbf{S}e^{-z\Gamma}\mathbf{S}^{-1} & 0 \end{pmatrix} = \begin{pmatrix} 0 & e^{-z\sqrt{\mathbf{Z}'\mathbf{Y}'}} \\ e^{-z\sqrt{\mathbf{Z}'\mathbf{Y}'}} & 0 \end{pmatrix}$$
(58)

**D** By (32) and (33), we have

$$\mathbf{v}_{+} = \frac{\mathbf{v} + \mathbf{Z}_{C} \,\mathbf{i}}{2} \qquad \qquad \mathbf{v}_{-} = \frac{\mathbf{v} - \mathbf{Z}_{C} \,\mathbf{i}}{2} \tag{59}$$

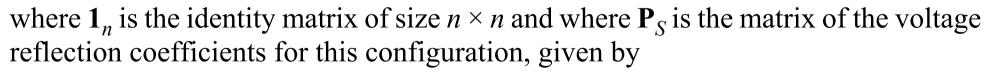
#### Matched termination circuit 9 and pseudo-matched terminations

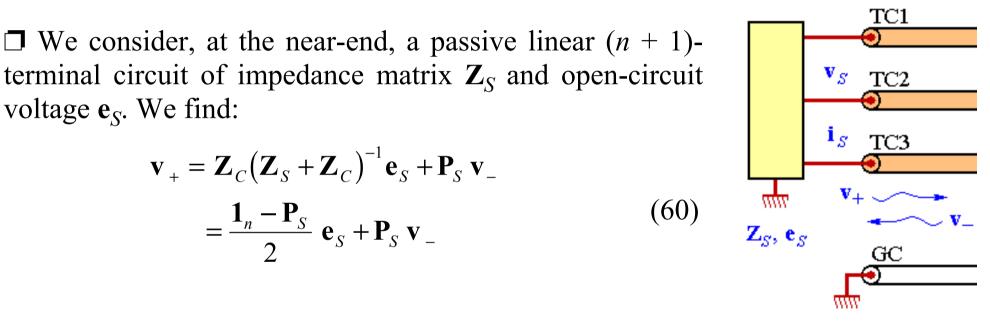
 $\mathbf{v}_{\perp} = \mathbf{Z}_{C} (\mathbf{Z}_{S} + \mathbf{Z}_{C})^{-1} \mathbf{e}_{S} + \mathbf{P}_{S} \mathbf{v}_{\perp}$ 

 $=\frac{\mathbf{1}_n-\mathbf{P}_S}{2}\mathbf{e}_S+\mathbf{P}_S\mathbf{v}_-$ 

voltage  $\mathbf{e}_{S}$ . We find:

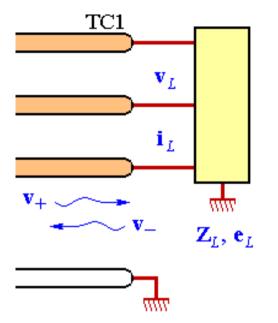
(61)











□ For the corresponding case at the far-end, we find:

$$\mathbf{v}_{-} = \mathbf{Z}_{C} (\mathbf{Z}_{L} + \mathbf{Z}_{C})^{-1} \mathbf{e}_{L} + \mathbf{P}_{L} \mathbf{v}_{+}$$
$$= \frac{\mathbf{1}_{n} - \mathbf{P}_{L}}{2} \mathbf{e}_{L} + \mathbf{P}_{L} \mathbf{v}_{+}$$
(62)

where  $\mathbf{P}_L$  is the matrix of the voltage reflection coefficients for this configuration, given by

$$\mathbf{P}_{L} = \mathbf{Z}_{C} (\mathbf{Z}_{L} + \mathbf{Z}_{C})^{-1} (\mathbf{Z}_{L} - \mathbf{Z}_{C}) \mathbf{Z}_{C}^{-1} = (\mathbf{Z}_{L} - \mathbf{Z}_{C}) (\mathbf{Z}_{L} + \mathbf{Z}_{C})^{-1}$$
(63)

□ A matched termination circuit produces no reflection:

♦ at the far-end, if Z<sub>L</sub> = Z<sub>C</sub> or equivalently P<sub>L</sub> = 0<sub>nn</sub>;
♦ at the near-end, if Z<sub>S</sub> = Z<sub>C</sub> or equivalently P<sub>S</sub> = 0<sub>nn</sub>.

 $\square$  Note that we are again referring to reflectionless matching, as opposed to hermitian matching which provides maximum power transfer [3].



□ For an interconnection in which TC-to-TC coupling is not negligible, a matched termination circuit has a non-diagonal impedance matrix (with respect to the GC).

 $\Box$  A termination circuit made of *n* impedors each connected between a TC and the GC has a diagonal impedance matrix (with respect to the GC). In this context, the impedance of an impedor intended to minimize the detrimental effects of reflections is referred to as pseudo-matched-impedance [35] [37] [38].

 $\square$  Pseudo-matched impedances can be defined as the diagonal elements of  $\mathbb{Z}_C[10]$  [12]. This is an arbitrary definition.

 $\square$  A second definition of pseudo-matched impedances requires that the diagonal elements of  $\mathbf{P}_L$  or  $\mathbf{P}_S$  are equal to zero. This is referred to as *diagonal matching* [20].

□ In diagonal matching, if the incident wave exists on a single TC, there is no reflected wave on this TC. Consequently, the termination circuit produces crosstalk, but no echo (however, it may indirectly contribute to echo).



□ A third definition of pseudo-matched impedances requires that the maximum (absolute) column sum norm  $|||\mathbf{P}|||_1$  of  $\mathbf{P} = \mathbf{P}_S$  or  $\mathbf{P} = \mathbf{P}_L$  be minimized. If  $\mathbf{P} = [\rho_{\alpha\beta}]$ , this matrix norm [8, § 5.6.4] [21, p. 1148] is defined by

$$\left\| \left\| \mathbf{P} \right\| \right\|_{1} = \max_{j} \sum_{i=1}^{n} \left| \boldsymbol{\rho}_{ij} \right|$$
(64)

 $\Box \| \| \bullet \| \|_1$  is the matrix norm induced by the L<sub>1</sub>-norm for vectors, defined by

$$\left\|\mathbf{v}\right\|_{1} = \sum_{i=1}^{n} \left|v_{i}\right| \tag{65}$$

Thus, for a non-zero incident wave **v** 

$$\frac{\left\|\mathbf{P}\,\mathbf{v}\right\|_{1}}{\left\|\mathbf{v}\right\|_{1}} \le \max_{\mathbf{x}\neq\mathbf{0}_{n1}} \frac{\left\|\mathbf{P}\,\mathbf{x}\right\|_{1}}{\left\|\mathbf{x}\right\|_{1}} = \left\|\left\|\mathbf{P}\,\right\|\right\|_{1}$$
(66)



□ A fourth definition of pseudo-matched impedances requires that the maximum (absolute) row sum norm  $|||\mathbf{P}|||_{\infty}$  of  $\mathbf{P} = \mathbf{P}_S$  or  $\mathbf{P} = \mathbf{P}_L$  be minimized. If  $\mathbf{P} = [\rho_{\alpha\beta}]$ , this matrix norm is defined by

$$\left\| \left\| \mathbf{P} \right\| \right\|_{\infty} = \max_{i} \sum_{j=1}^{n} \left| \boldsymbol{\rho}_{ij} \right|$$
(67)

 $\Box \, \||\!\!||_{\infty}$  is the matrix norm induced by the  $L_{\infty}\text{-norm}$  for vectors, defined by

$$\|\mathbf{v}\|_{\infty} = \max_{i} |v_{i}| \tag{68}$$

Thus, for a non-zero incident wave v

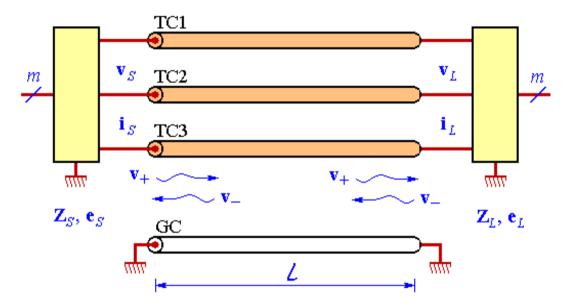
$$\frac{\|\mathbf{P} \mathbf{v}\|_{\infty}}{\|\mathbf{v}\|_{\infty}} \le \max_{\mathbf{x} \neq \mathbf{0}_{n1}} \frac{\|\mathbf{P} \mathbf{x}\|_{\infty}}{\|\mathbf{x}\|_{\infty}} = |||\mathbf{P}|||_{\infty}$$
(69)

 $\Box$  In the special case where losses are neglected,  $Z_C$  is real and frequency-independent, so that the pseudo-matched impedances are resistances.



### 10. Problems involving an MTL and linear terminations

In this configuration,  $\mathbf{e}_S$  and  $\mathbf{e}_L$  are the vectors of the open-circuit voltages at the near-end and at the far-end, respectively.



 $\Box$  Three possible approaches to find  $\mathbf{v}_S$  and  $\mathbf{v}_L$  in the configuration shown above:

- using the boundary conditions to obtain  $\mathbf{v}_{M0^+}$ ,  $\mathbf{v}_{M0^-}$ ,  $\mathbf{i}_{M0^+}$  and  $\mathbf{i}_{M0^-}$  in (24) and (26);
- $\blacklozenge$  using the scattering matrix defined by (58) and the reflection coefficients;
- using the chain matrix (not studied in this tutorial).



**\Box** Following the second approach, we consider multiple reflections occurring at the ends and multiple propagation through the MTL. For case  $\mathbf{e}_S \neq \mathbf{0}$  and  $\mathbf{e}_L = \mathbf{0}$ , we get:

$$\mathbf{v}_{+}(0) = \left\{ \sum_{p=0}^{\infty} \left( \mathbf{P}_{S} e^{-\mathcal{L}\sqrt{\mathbf{Z}'\mathbf{Y}'}} \mathbf{P}_{L} e^{-\mathcal{L}\sqrt{\mathbf{Z}'\mathbf{Y}'}} \right)^{p} \right\} \mathbf{Z}_{C} \left( \mathbf{Z}_{S} + \mathbf{Z}_{C} \right)^{-1} \mathbf{e}_{S}$$

$$\left\{ \mathbf{v}_{+}(\mathcal{L}) = e^{-\mathcal{L}\sqrt{\mathbf{Z}'\mathbf{Y}'}} \left\{ \sum_{p=0}^{\infty} \left( \mathbf{P}_{S} e^{-\mathcal{L}\sqrt{\mathbf{Z}'\mathbf{Y}'}} \mathbf{P}_{L} e^{-\mathcal{L}\sqrt{\mathbf{Z}'\mathbf{Y}'}} \right)^{p} \right\} \mathbf{Z}_{C} \left( \mathbf{Z}_{S} + \mathbf{Z}_{C} \right)^{-1} \mathbf{e}_{S}$$

$$(70)$$

and

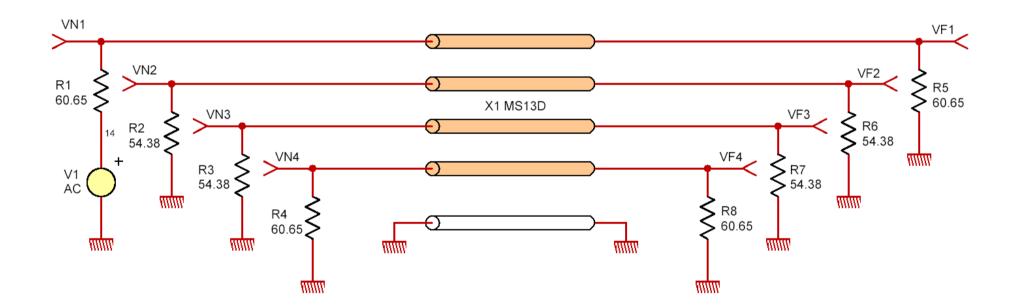
$$\begin{cases} \mathbf{v}_{S} = \begin{bmatrix} \mathbf{1}_{n} + e^{-\mathcal{L}\sqrt{\mathbf{Z}'\mathbf{Y}'}} \mathbf{P}_{L} e^{-\mathcal{L}\sqrt{\mathbf{Z}'\mathbf{Y}'}} \end{bmatrix} \mathbf{v}_{+}(0) \\ \mathbf{v}_{L} = \begin{bmatrix} \mathbf{1}_{n} + \mathbf{P}_{L} \end{bmatrix} \mathbf{v}_{+}(\mathcal{L}) \end{cases}$$
(71)

Using [8, § 5.6.16], we obtain

$$\begin{cases} \mathbf{v}_{S} = \left(\mathbf{1}_{n} + e^{-\mathcal{L}\sqrt{\mathbf{Z}'\mathbf{Y}'}} \mathbf{P}_{L} e^{-\mathcal{L}\sqrt{\mathbf{Z}'\mathbf{Y}'}}\right) \left(\mathbf{1}_{n} - \mathbf{P}_{S} e^{-\mathcal{L}\sqrt{\mathbf{Z}'\mathbf{Y}'}} \mathbf{P}_{L} e^{-\mathcal{L}\sqrt{\mathbf{Z}'\mathbf{Y}'}}\right)^{-1} \mathbf{Z}_{C} \left(\mathbf{Z}_{S} + \mathbf{Z}_{C}\right)^{-1} \mathbf{e}_{S} \\ \mathbf{v}_{L} = \left(\mathbf{1}_{n} + \mathbf{P}_{L}\right) e^{-\mathcal{L}\sqrt{\mathbf{Z}'\mathbf{Y}'}} \left(\mathbf{1}_{n} - \mathbf{P}_{S} e^{-\mathcal{L}\sqrt{\mathbf{Z}'\mathbf{Y}'}} \mathbf{P}_{L} e^{-\mathcal{L}\sqrt{\mathbf{Z}'\mathbf{Y}'}}\right)^{-1} \mathbf{Z}_{C} \left(\mathbf{Z}_{S} + \mathbf{Z}_{C}\right)^{-1} \mathbf{e}_{S} \end{cases}$$
(72)

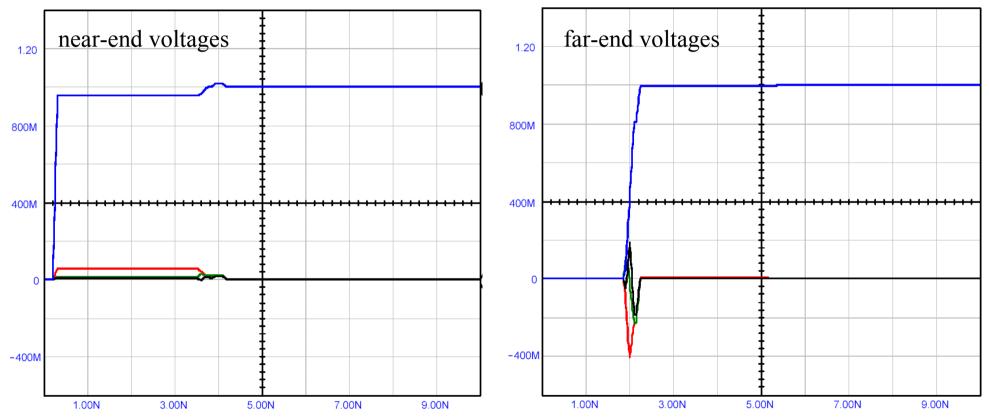


□ Example: a 300-mm long multiconductor microstrip built on FR-4, having 4 TCs, used for single-ended transmission with pseudo-matched terminations such that  $|||\mathbf{P}_{S}|||_{\infty} = |||\mathbf{P}_{L}|||_{\infty} \approx 0.130$  and  $|||\mathbf{P}_{S}|||_{1} = |||\mathbf{P}_{L}|||_{1} \approx 0.138$ .





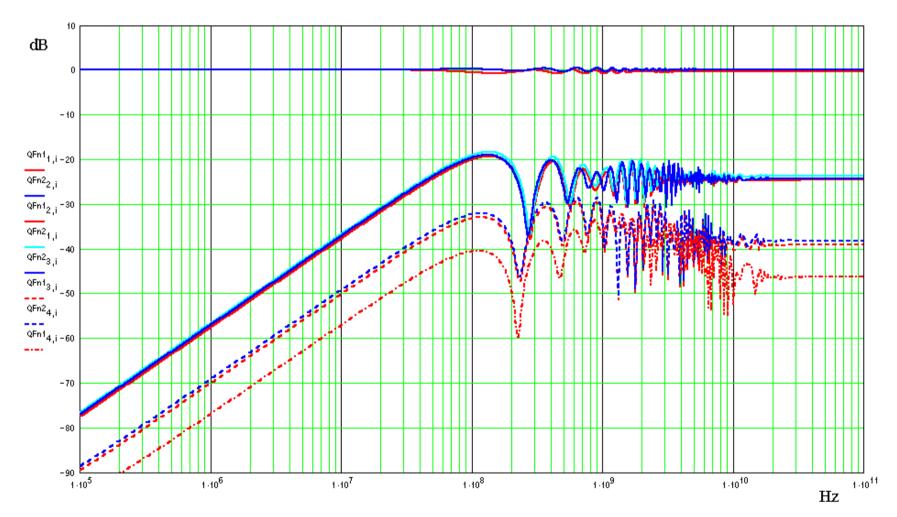
# Simulation using a circuit simulation program (based on Berkeley SPICE 3F.2) and a lossless MTL model generated by SpiceLine [10] [12] [16] [22].



Voltages in mV versus time in ns. TC1: blue curves. TC2: red curves. TC3: green curves. TC4: black curves.

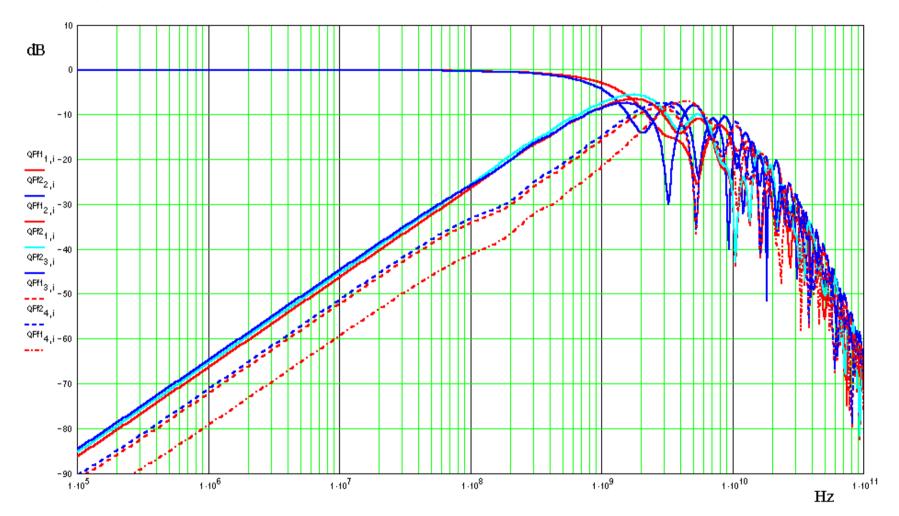


In the frequency domain, some voltages at the near-end, computed with a standard calculation software, resistive and dielectric losses being taken into account



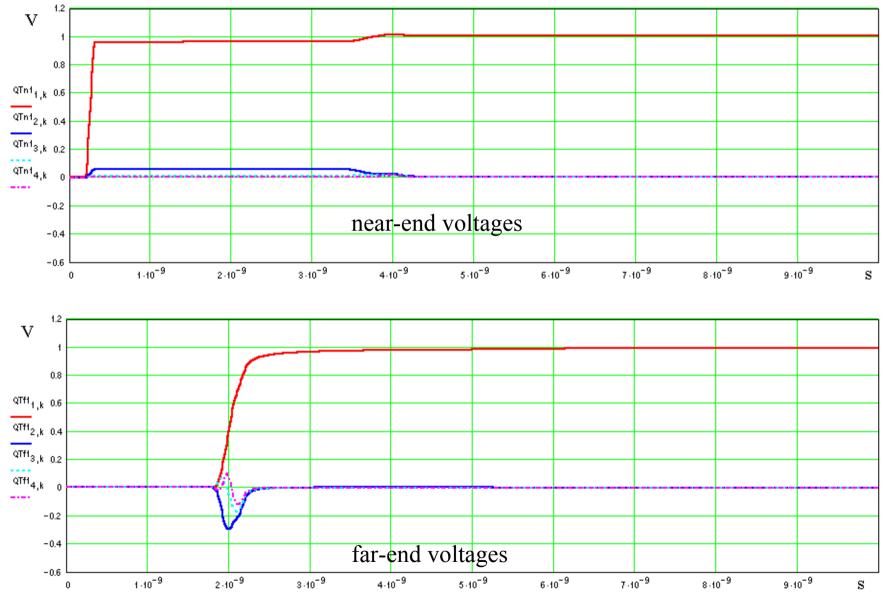


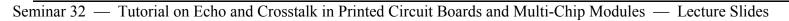
Some voltages at the far-end, computed with the same tool, resistive and dielectric losses being taken into account.



Time domain results using the same tool, resistive and dielectric losses being taken into account.









## 11. The degradation of transmitted signals

☐ The degradation of signals transmitted through a linear link is the result of five phenomena:

◆ *attenuation* in the interconnection;

◆ *linear distortions*, caused by the variation of attenuation and propagation velocity with frequency (dispersion);

 $\blacklozenge$  *echo*, the detrimental phenomenon by which a signal propagating applied at an end of the link, in one of the transmission channels, produces a noise on the same transmission channel, at the same end of the link;

◆ *internal crosstalk*, the detrimental phenomenon by which a signal sent in one of the transmission channels produces noise in another transmission channel;

 $\blacklozenge$  thermal noise.

 $\square$  We have not included the *propagation delay* in this list, but this phenomenon might also be a problem.



 $\Box$  In the case of a signal applied at the near-end,

- ◆ *near-end crosstalk* (NEXT) is the internal crosstalk occurring at the near-end;
- ♦ *far-end crosstalk* (FEXT) is the internal crosstalk occurring at the far-end.

 $\Box$  *Reflection* is the phenomenon by which a wave propagating in a given direction, in one or more TCs, produces a wave on the same TCs, propagating in the opposite direction.

□ Reflections may be responsible for echo and/or internal crosstalk.

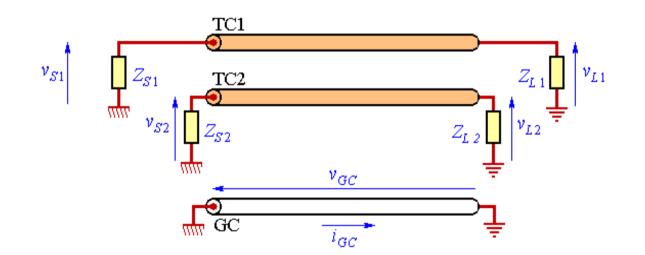
 $\Box$  If the interconnection is uniform, reflection can only be caused by the items connected at its ends.

 $\Box$  *TC-to-TC coupling* is the phenomenon caused by mutual inductance and mutual capacitance between the TCs.

**TC-to-TC** coupling may be responsible for internal crosstalk.



 $\Box$  External crosstalk is often associated with a current  $i_{GC}$  flowing in the GC because of such other circuit, causing a voltage drop  $v_{GC}$  along the GC, often referred to as ground shift or noisy ground.



☐ This concept is valid at dc and very low frequencies, but it is not compatible with the MTL model.



□ This is not a deficiency of the MTL model:

◆ at high frequencies, the voltages between the conductors are defined unambiguously only in a cross-section of the interconnection;

• a TC must be added to allow  $i_{GC}$  to flow, and included in the MTL model.

□ Possible causes of external crosstalk degrading transmission in a given link:

- ◆ a conductor parallel to the interconnection, excited at the near-end;
- ◆ a conductor parallel to the interconnection, excited at the far-end;
- ◆ a conductor crossing the interconnection (below or above the TCs);
- ◆ common-mode coupling at the near-end (sending end);
- ◆ common-mode coupling at the far-end (receiving end).

□ The mitigation techniques for internal crosstalk apply to the first two cases.



Crossing at a right angle produces a local coupling, which can often be modeled with a circuit model only comprising stray capacitances.

Common-mode coupling at the near-end or at the far-end typically happens in the line drivers or line receivers of an IC, because of currents produced by other circuits of the IC, flowing in a common impedance (e.g. the so-called *ground bounce*).

☐ The common impedance is often caused by mutual inductance in the reference or power supply conductors within the IC package, or the corresponding leads.

☐ The currents having the worst effects are often caused by multiple switching in the IC, e.g. the so-called *simultaneous switching output* (SSO) noise.

□ Once the common impedance has been reduced to the smaller practical value, a crosstalk cancellation scheme must be used to reduce external noise in the channel.



### 12. Single-ended parallel links

□ *Single-ended transmission*: any transmission scheme in which a single TC is allocated to each channel, and in which a global net such as GND or VCC, referred to as the GC, is used as a voltage reference for receiving signals.

A *single-ended link* uses single-ended transmission. It must be such that

◆ TC-to-TC coupling is small;

 $\blacklozenge$  the near-end interface and termination device (NIT) and the far-end interface and termination device (FIT) do not introduce any significant couplings between the voltages and currents in the TCs.

☐ Thus, for small signals, in any state, the impedance matrices of the NIT and FIT with respect to ground may be regarded as diagonal (or almost diagonal) matrices.



□ A single-ended link may use:

- ◆ voltage-mode signaling (low impedance NIT, high impedance FIT);
- ◆ current-mode signaling (high impedance NIT, low impedance FIT);
- ◆ pseudo-matched impedances at the NIT and/or at the FIT.

□ Voltage-mode and current mode circuits can be used in the line drivers and line receivers of different types of single-ended links. For instance:

◆ a voltage-mode line driver fitted with a series resistor (series termination) can provide a suitable pseudo-matched impedance;

◆ a current-mode line driver or a voltage-mode line receiver fitted with a parallel termination can provide a suitable pseudo-matched impedance.

□ A single-ended link can be point-to-point or multidrop.



□ Each TC of a single-ended point-to-point link can be used for unidirectional (simplex) transmission, alternate bidirectional (half duplex) transmission or simultaneous bidirectional (full duplex) transmission.

 $\square$  Each TC of a single-ended multidrop link can be used for unidirectional transmission or as a bus.

☐ The interconnection model underlying the concept of single-ended links excludes TC-to-TC coupling. Thus, possible models are:

♦ one ideal node for each TC, in the case of a short interconnection;

◆ a lumped elements model for each TC for longer but electrically short interconnections;

 $\blacklozenge$  a TL model for each TC;

◆ a uniform TL model for each TC if the interconnection is uniform.



□ Since the underlying interconnection model does not include TC-to-TC coupling, actual non-zero TC-to-TC coupling is likely to produce crosstalk.

□ In the case  $n \ge 2$ , it is advisable to take TC-to-TC coupling into account at the analysis stage. It is possible to use:

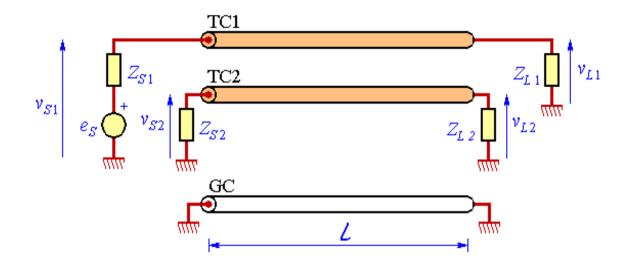
◆ a lumped element model for an electrically short interconnection;

- ◆ the weak coupling approximation applied to a lossless MTL model;
- ◆ an exact solution of a lossless MTL model;
- ◆ an exact solution of a MTL model taking losses into account.

The weak coupling approximation provides closed-form solutions which reveal the underlying physics and can be used for comparing design options.

 $\Box$  We can use a first order perturbation theory where the undisturbed solution corresponds to uncoupled TLs.





 $\square$  For the single-ended link shown, let us assume a uniform and lossless interconnection such that

$$\mathbf{Z'} = j\omega \begin{pmatrix} L'_{11} & L'_{12} \\ L'_{12} & L'_{22} \end{pmatrix} \quad \text{and} \quad \mathbf{Y'} = j\omega \begin{pmatrix} C'_{11} & C'_{12} \\ C'_{12} & C'_{22} \end{pmatrix}$$
(73)

□ Let us define

$$Z_{01} = \sqrt{\frac{L'_{11}}{C'_{11}}} , \quad Z_{02} = \sqrt{\frac{L'_{22}}{C'_{22}}} , \quad c_1 = \frac{1}{\sqrt{L'_{11}C'_{11}}} \quad \text{and} \quad c_2 = \frac{1}{\sqrt{L'_{22}C'_{22}}}$$
(74)

which would be characteristic impedances and propagation velocities if coupling was not present.



 $\Box$  Let us define the capacitive coupling coefficient  $\xi_2$  and the relative magnetic coupling coefficient  $\Xi_2$  as:

$$\xi_2 = -\frac{C'_{12}}{C'_{22}}$$
 and  $\Xi_2 = -\frac{L'_{12}C'_{11}}{L'_{22}C'_{12}}$  (75)

**T** For  $Z_{S1} = Z_{L1} = Z_{01}$ ,  $Z_{S2} = Z_{L2} = Z_{02}$  and  $c_1 = c_2 = c$ , we get the result of Jarvis [2]:

$$v_{S2} = \frac{e_S \xi_2}{8} (\Xi_2 + 1) \left( 1 - e^{-2j \frac{\omega}{c} L} \right)$$
(76)

$$v_{L2} = -j\frac{\omega}{c} \frac{e_{S}\xi_{2}}{4} (\Xi_{2} - 1)\mathcal{L} e^{-j\frac{\omega}{c}\mathcal{L}}$$
(77)

 $\Box \text{ We can check that the maximum value of } |v_{S2}/v_{L1}| \text{ is } \frac{\xi_2}{2}(\Xi_2 + 1), \text{ first achieved at}$  $\omega = \frac{\pi c}{2L}. \text{ This maximum is independent of } L.$ 



□ In the time domain, in the same case, the Jarvis formulas are:

$$v_{S2}(t) = \frac{\xi_2}{8} (\Xi_2 + 1) \left( e_S(t) - e_S\left(t - \frac{2\mathcal{L}}{c}\right) \right)$$
(78)

and

$$v_{L2}(t) = -\frac{\xi_2}{4c} (\Xi_2 - 1) \mathcal{L} \frac{de_s}{dt} \left( t - \frac{\mathcal{L}}{c} \right)$$
(79)

**This approximation predicts that:** 

1

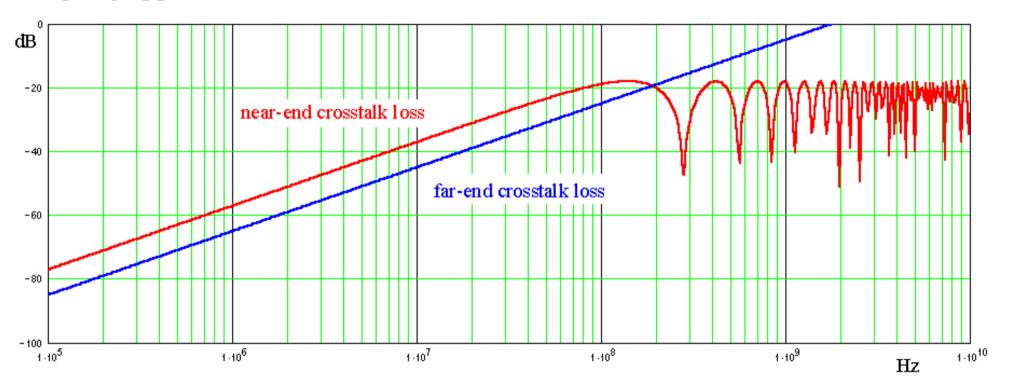
- $v_{S2}(t)$  is proportional to  $e_S(t) e_S(t 2L/c)$  and otherwise independent of L;
- $\blacklozenge$  the form of (76) or (78) shows that a reflection takes place at the far end;
- $v_{L2}(t)$  is proportional to L and to the time derivative of  $e_S(t L/c)$ ;
- $v_{L2}(t)$  vanishes for  $\Xi_2 = 1$ ;
- $\blacklozenge$  thus, for  $\Xi_2 = 1$ , we have a *directional coupling*.

 $\Box$  In a multiconductor stripline structure, we have  $\Xi_2 = 1$ . In a multiconductor microstrip structure, we have  $\Xi_2 > 1$ .



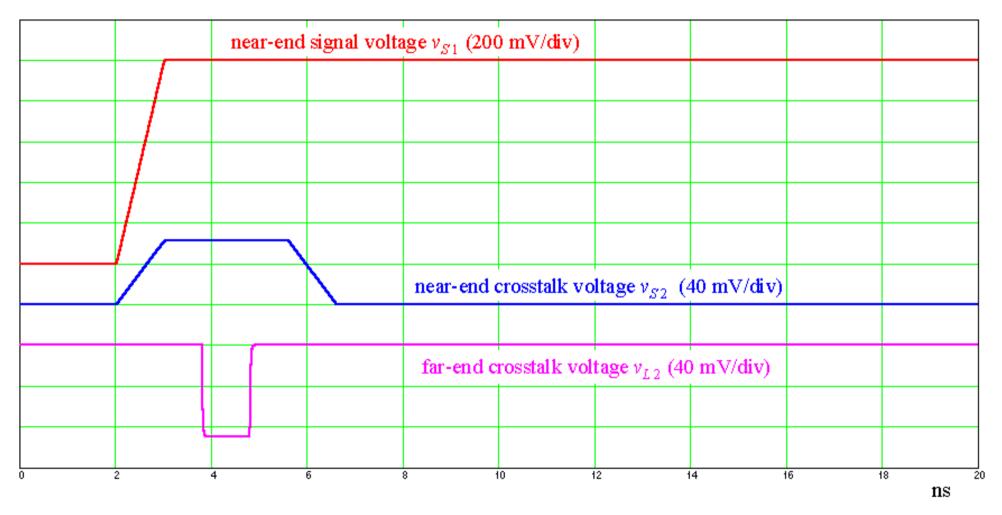
### $\Box Z_{01}$ and $Z_{02}$ are not characteristic impedances but pseudo-matched impedances.

□ An example of NEXT loss  $|v_{L1}/v_{S2}|$  and FEXT loss  $|v_{L1}/v_{L2}|$  in a 300-mm long multiconductor microstrip built on FR-4, having 2 TCs, according to the weak coupling approximation.





In the time domain, for the step having 0%-100% rise time of 1 ns, we obtain the classical waveforms of this approximation:





 $\Box$  If we do not assume  $Z_{S1} = Z_{L1} = Z_{01}$ , it is useful to define the parameters

$$\rho_{S1} = \frac{Z_{S1} - Z_{01}}{Z_{S1} + Z_{01}} \quad \text{and} \quad \rho_{L1} = \frac{Z_{L1} - Z_{01}}{Z_{L1} + Z_{01}}$$

$$K_{MR1} = \sum_{p=0}^{\infty} \left( \rho_{S1} \rho_{L1} e^{-2j \frac{\omega}{c_1} L} \right)^p = \frac{1}{1 - \rho_{S1} \rho_{L1}} e^{-2j \frac{\omega}{c_1} L}$$
(80)
(81)

and

 $\Box$  If we do not assume  $Z_{S2} = Z_{L2} = Z_{02}$ , it is useful to define the parameters

$$\rho_{S2} = \frac{Z_{S2} - Z_{02}}{Z_{S2} + Z_{02}} \quad \text{and} \quad \rho_{L2} = \frac{Z_{L2} - Z_{02}}{Z_{L2} + Z_{02}}$$

$$K_{MR2} = \sum_{p=0}^{\infty} \left( \rho_{S2} \rho_{L2} e^{-2j \frac{\omega}{c_2} \ell} \right)^p = \frac{1}{1 - \rho_{S2} \rho_{L2} e^{-2j \frac{\omega}{c_2} \ell}}$$
(82)
(83)

and



 $\Box$  If we only assume negligible losses, weak coupling and  $c_1 = c_2 = c$ , we get:

$$v_{S2} = \frac{e_{S}(1-\rho_{S1})(1+\rho_{S2})K_{MR1}K_{MR2}\xi_{2}}{4} \begin{cases} \left(1+\rho_{L1}\rho_{L2}e^{-2j\frac{\omega}{c}L}\right)\frac{\Xi_{2}+1}{2}\left(1-e^{-2j\frac{\omega}{c}L}\right) \\ -(\rho_{L1}+\rho_{L2})\frac{j\omega}{c}(\Xi_{2}-1)Le^{-2j\frac{\omega}{c}L} \end{cases} \end{cases}$$

$$(84)$$

and

$$v_{L2} = \frac{e_{s}(1-\rho_{s1})(1+\rho_{L2})K_{MR1}K_{MR2}\xi_{2}}{4} \begin{cases} (\rho_{L1}+\rho_{s2})\frac{\Xi_{2}+1}{2}\left(1-e^{-2j\frac{\omega}{c}L}\right) \\ -\left(1+\rho_{L1}\rho_{s2}e^{-2j\frac{\omega}{c}L}\right)\frac{j\omega}{c}(\Xi_{2}-1)L \end{cases} e^{-j\frac{\omega}{c}L} \end{cases}$$

$$(85)$$



□ In the case where L is not electrically short, a practical link is such that, for reducing echo, the NIT of the FIT must provide a low reflection coefficient at at least one end of each TC. Thus, we can assume that  $K_{MR1} \approx 1$  and  $K_{MR2} \approx 1$ .

□ The internal crosstalk mitigation approaches taught by (84) and (85) are:

• increasing the distance between the TCs relative to the distance a TC and the GC, to obtain a decrease of  $\xi_{12}$ ;

• making  $\Xi_2$  close to 1;

• making  $Z_{L1}$  close to  $Z_{01}$  reduces the absolute value of 2 terms in (84) and 2 terms in (85);

• making  $Z_{L2}$  close to  $Z_{02}$  reduces the absolute value of 2 terms in (84);

- making  $Z_{S2}$  close to  $Z_{02}$  reduces the absolute value of 2 terms in (85);
- ◆ decreasing as much as possible the bandwidth of the line receivers;
- decreasing as much as possible the bandwidth of the line drivers.



 $\Box$  By (72), it appears that, for a lossless MTL, at a time  $t < 2 \tau_{\min}$  from an excitation,  $\mathbf{v}_S$  is only determined by  $\mathbf{Z}_C (\mathbf{Z}_S + \mathbf{Z}_C)^{-1} \mathbf{e}_S$ . This exact result is compatible with (78) and (84):  $\mathcal{L}$  plays no role and  $\omega$  plays no role except, possibly, in  $\mathbf{Z}_S$ .

 $\Box$  Using (72), it can be shown that, for a completely degenerate MTL seeing pseudomatched impedances at the ends of each TC, there is no FEXT to the first order in the weak coupling approximation. This result is compatible with (79).

□ Thus, in a long single-ended link terminated with pseudo-matched impedances,

- ◆ the cause of NEXT is the lack of matching at the near-end; and
- ◆ the cause of FEXT is the propagation of modes at unequal velocities.

 $\Box$  It is often difficult to use low-swing transmission in the single-ended links of a digital IC due to common-mode coupling at the near-end or at the far-end.

□ A compensation or equalization schemes used to flatten the channel gain in the bandwidth used for transmission unfortunately increase the FEXT.



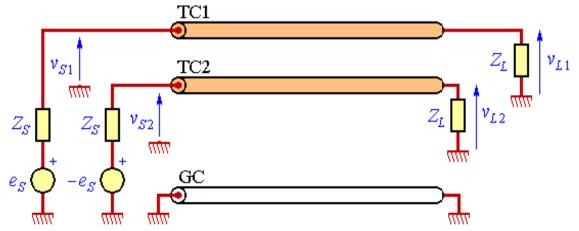
## 13. Multichannel differential links

□ A balanced pair comprises 2 TCs having the same *averaged* p.u.l. impedance and p.u.l. admittance with respect to the GC.

□ In a link using a 2-TC interconnection, a NIT or FIT is balanced if the signal terminals present the same admittance with respect to the GC.

 $\Box$  Using a balanced pair and balanced NIT and FIT, *it seems that* a differential-mode source and a common-mode source produce opposite and equal voltages with respect to the GC, respectively, at each *z*.

For instance, for  $L'_{11} = L'_{22}$ and  $C'_{11} = C'_{22}$ , in the link shown, by symmetry we have  $-v_{S2} = v_{S1}$  and  $-v_{L2} = v_{L1}$ .





□ A single-channel differential link uses this configuration with:

◆ a transmitting circuit using a differential-mode source for signaling (differential line driver); and

◆ a receiving circuit sensitive to differential mode signals and insensitive to the common-mode voltages (differential line receiver).

□ This crosstalk cancellation scheme reduces the effect of 3 causes of external crosstalk:

- $\blacklozenge$  a conductor crossing the interconnection;
- ◆ common-mode coupling at the near-end;
- ◆ common-mode coupling at the far-end.

 $\Box$  However, this is only true if other parallel conductors do not disturb the requirement  $L'_{11} \approx L'_{22}$  and  $C'_{11} \approx C'_{22}$ . For instance, the following geometry may cause problems:





□ A perfectly balanced pair comprises 2 TCs such that [49]:

♦ the TCs have the same *averaged* p.u.l. impedance and p.u.l. admittance with respect to the GC;

 $\blacklozenge$  the excitation of the pair in differential mode induces no voltage and injects no current in any other conductor.

By reciprocity, a voltage appearing on or a current flowing in such other conductor produces no differential mode excitation in the perfectly balanced pair.

□ A differential link using a perfectly balanced pair reduces the effect of all causes of external crosstalk.

□ The second condition for a perfectly balanced pair may be satisfied using a sufficient distance from other parallel conductors, or using a frequent twisting [30]:





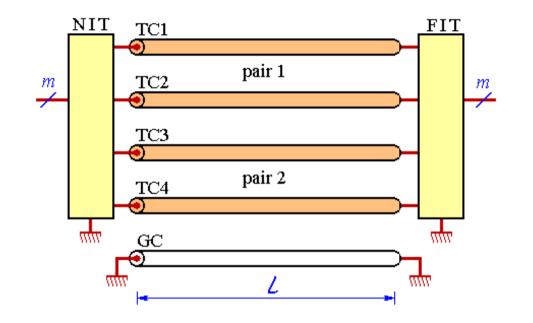
 $\Box$  The twisted pair behaves as a uniform interconnection only if the length of a twist is much smaller than the wavelength, hence the used of *averaged* in the definitions.

□ A perfectly balanced interconnection comprises *p* pairs such that [49]:

- ◆ the TCs of the same pair have the same *averaged* p.u.l. impedance and p.u.l. admittance with respect to the GC;
- ◆ the excitation of any pair in differential mode induces no voltage and injects no current in any other conductor.
- ☐ The second condition for a perfectly interconnection pair may be satisfied using a sufficient distance from other parallel conductors, or using a frequent transposition of the TCs of each pair.

□ In transposition, the TCs of each pair exchange position at intervals along the line so as to balance out, as exactly as possible, unwanted voltages and currents induced by adjacent circuits, while complying with the first condition.





□ *Differential transmission*: any transmission scheme in which two TCs (*a pair*), a differential line driver and a differential line receiver are allocated to each channel.

A *multichannel differential link* uses differential transmission. It must be such that:

- ◆ the interconnection nearly behaves as a perfectly balanced interconnection;
- $\blacklozenge$  each pair of signal terminals of the NIT or of the FIT, intended to be connected to an end of a single pair, is nearly balanced.



□ Note that TC-to-TC coupling is not a problem:

- ♦ between the TCs of the same pair;
- ♦ if it occurs between the TCs of different pairs, if it is balanced out.

☐ This crosstalk cancellation scheme reduces internal crosstalk.

□ This crosstalk cancellation scheme reduces the effect of all causes of external crosstalk, if the link uses a perfectly balanced interconnection.

□ A differential link can be point-to-point or multidrop.

□ Each pair of a differential point-to-point link can be used for unidirectional (simplex) transmission, alternate bidirectional (half duplex) transmission or simultaneous bidirectional (full duplex) transmission.

□ Each pair of a differential multidrop link can be used for unidirectional transmission or as a bus.



 $\square$  For *p* pairs, for  $\alpha \in \{1, ..., p\}$ , we can define

- $\blacklozenge p$  differential-mode voltages
- $\blacklozenge p$  differential-mode currents
- $\blacklozenge p$  pair common-mode voltages
- $\blacklozenge p$  pair common-mode currents

```
v_{DM\alpha} = v_{2\alpha - 1} - v_{2\alpha};

i_{DM\alpha} = (i_{2\alpha - 1} - i_{2\alpha})/2;

v_{CM\alpha} = (v_{2\alpha - 1} + v_{2\alpha})/2;

i_{CM\alpha} = i_{2\alpha - 1} + i_{2\alpha}.
```

□ We do not imply that these variables are propagation modes of the interconnection.

□ It can be shown that, for a perfectly balanced interconnection:

◆ the differential-mode voltages and the differential-mode currents are propagation modes of the interconnection;

◆ thus, there is no coupling between the differential-mode variables of a pair and the differential-mode or pair common-mode variables of another pair;

◆ thus, in the case of an ideal NIR and of an ideal FIR, there is no internal crosstalk.



□ In a densely wired PCB or MCM, the interconnection is often far from being perfectly balanced.

☐ The interconnection model underlying the concept of differential links excludes any coupling between the differential-mode variables of a pair and currents or voltages on other conductors. Thus, possible models are:

♦ one ideal node for each TC, in the case of a short interconnection;

♦ a lumped elements model for each pair, in the case of a longer but electrically short interconnections;

◆ a 3-conductor MTL model for each pair;

◆ a uniform 3-conductor MTL model for each pair, if the interconnection is uniform;

◆ a TL model for the differential-mode variable of each pair;

 $\blacklozenge$  a uniform TL model for the differential-mode variable of each pair, if the interconnection is uniform.



□ Since the underlying interconnection model excludes the couplings between the differential-mode variables on a pair and the differential-mode or pair common-mode variables relating to another pair, actual non-zero values of these couplings are likely to produce crosstalk.

 $\Box$  In the case  $n \ge 2$ , it is advisable to take TC-to-TC coupling into account at the analysis stage. It is possible to use:

- ◆ a lumped element model for an electrically short interconnection;
- ◆ an exact solution of a lossless MTL model using natural variables;

♦ an exact solution of a lossless MTL model using the differential-mode and common-mode variables;

◆ an exact solution of a MTL model taking losses into account;

♦ an exact solution of a MTL model using the differential-mode and commonmode variables and taking losses into account.



□ In the usual case where transposition is not used, a discussion of the design options for a multichannel differential link must take into account:

- ◆ the types of pairs (microstrip, edge-coupled stripline, broadside-coupled stripline, ...) and the tightness of the coupling between the TCs of each pair;
- ◆ the relative position of the pairs;
- the type of termination for each pair (unterminated, pseudo-matched, floating,  $\pi$ , Y);
- ♦ the type of differential line driver and differential line receivers (voltagemode, current mode [51] [81] [87]).
- $\Box$  A differential link of a digital IC can use low-swing transmission if it is sufficiently immune to common-mode coupling at the near-end and at the far-end.

A wide-band differential link can use a compensation or equalization schemes to flatten the channel gain, if the high-frequency crosstalk is sufficiently low [80].



# 14. Modal signaling

 $\Box$  Up to now, we have considered the modal decomposition as a step in the MTL theory used for computing voltages and currents in a uniform multiconductor interconnection having *n* TCs.

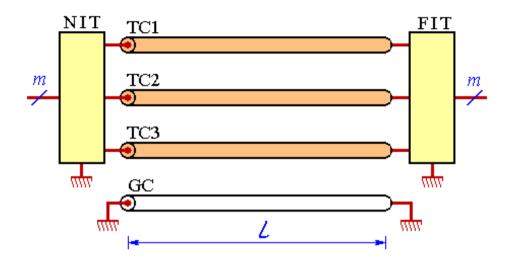
 $\Box$  In § 4, we used

$$\begin{cases} \mathbf{v}_{M} = e^{-z\Gamma} \, \mathbf{v}_{M0+} + e^{z\Gamma} \, \mathbf{v}_{M0-} \\ \mathbf{i}_{M} = e^{-z\Gamma} \, \mathbf{i}_{M0+} + e^{z\Gamma} \, \mathbf{i}_{M0-} \end{cases}$$
(26)

where  $\mathbf{v}_{M0^+}$ ,  $\mathbf{v}_{M0^-}$ ,  $\mathbf{i}_{M0^+}$  and  $\mathbf{i}_{M0^-}$  are *z*-independent vectors. We see that propagation entails an alteration of  $\mathbf{v}_{M^+} = e^{-z\Gamma} \mathbf{v}_{M0^+}$ ,  $\mathbf{v}_{M^-} = e^{z\Gamma} \mathbf{v}_{M0^-}$ ,  $\mathbf{i}_{M^+} = e^{-z\Gamma} \mathbf{i}_{M0^+}$  and  $\mathbf{i}_{M^-} = e^{z\Gamma} \mathbf{i}_{M0^-}$ , but no interference between the entries of each of these vectors.

**This suggests a modal signaling method for removing crosstalk in a** *m***-channel link using a uniform multiconductor interconnection having**  $n \ge m$  TCs.





□ In modal signaling :

◆ for each of the *m* transmission channels, we use a modal electrical variable (modal voltage or modal current), instead of a natural electrical variable (natural voltage or a natural current) in single-ended signaling;

♦ the modal electrical variables used for transmission are all modal voltages or all modal currents;

 $\blacklozenge$  the NIR and the FIR must perform the necessary conversion, which are defined by a transition matrix from modal electrical variables to natural electrical variable, i.e., **S** or **T**.



 $\square$  A differential link implements modal signaling, for m = 1 and n = 2. In this case, **S** and **T** are determined by the symmetry of the interconnection so that:

- ◆ they are frequency-independent;
- $\mathbf{v}_M$  and  $\mathbf{i}_M$  are easily defined in the time and frequency domains.

 $\Box$  In most multiconductor interconnections such that  $n \ge 3$ , S and T are not fully determined by the symmetries and are frequency dependent complex matrices.

□ A simplified definition of the general ZXtalk method reads as follows:

 $\blacklozenge$  for each of the *m* transmission channels, we use a modal voltage or a modal current (modal signaling);

♦ the interconnection has *n* TCs, with  $n \ge m$ , and it is terminated with at least one matched termination, i.e. a (n + 1)-terminal linear termination circuit having an impedance matrix approximating  $\mathbf{Z}_{C}$ .



☐ According to this simplified definition of the general ZXtalk method, no internal crosstalk and no echo occurs in the transmission channels since:

◆ the total decoupling provides an independent propagation of each eigenvoltage with the associated eigen-current;

 $\blacklozenge$  the termination circuits absorb incident waves so that they do not create couplings between the modes.

□ According to this simplified definition, at each frequency used for transmission,

 $\blacklozenge$  a transmitting circuit (TX circuit) must combine the input signals according to linear combinations defined by **S** or **T**;

♦ a receiving circuit (RX circuit) must combine the signals present on the TCs according to linear combinations defined by  $S^{-1}$  or  $T^{-1}$ .

 $\Box$  Unfortunately, it is difficult to perform the modal variable to natural variable conversion when **S** and **T** are frequency dependent complex matrices.



□ In the RC region, we may consider that  $\mathbf{Z} \approx \mathbf{R}$  and  $\mathbf{Y} \approx j\omega \mathbf{C}$  where **R** and **C** are frequency-independent matrices. Thus,

•  $\mathbf{Z}_C$  is in the form  $\mathbf{Z}_C \approx \frac{1-j}{\sqrt{2\omega}} \mathbf{A}_C$  (86)

where  $A_C$  is a real and frequency-independent matrix;

 $\blacklozenge$  this  $\mathbf{Z}_C$  cannot be realized accurately over a wide relative bandwidth, using a lumped termination circuit;

 $\blacklozenge$  we are in trouble to implement the simplified definition of the general ZXtalk method at low frequencies.

#### □ However,

◆ a reduction of crosstalk or echo is not needed at low frequencies;

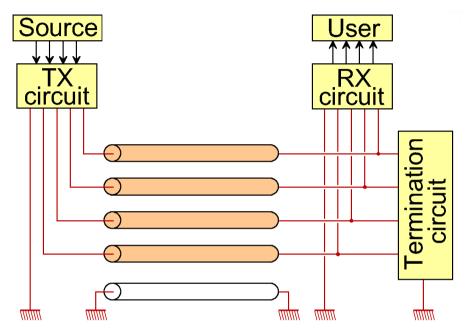
♦ the simplified definition of the general ZXtalk method is easy to implement in the LC region and at higher frequencies where  $Z_C$  is real and frequencyindependent, and where S and T may be chosen real and frequency-independent.



 $\Box$  A more general definition of the general ZXtalk method [27] [28] relates to an *m*-channel link such that:

♦ the interconnection has *n* TCs, with  $n \ge m$ , and may be modeled as a uniform (n + 1)-conductor MTL, with a sufficient accuracy, in a known frequency band;

• the interconnection is connected at at least one end to a termination circuit having, in the known frequency band, an impedance matrix near  $\mathbf{Z}_C$ ;



◆ a TX circuit delivers modal electrical variables defined by **S** or **T**, each modal electrical variable being mainly determined by one and only one input signal;

◆ a RX circuit delivers output signals, each of the output signals being mainly determined by one and only one of said modal electrical variables.

☐ The "known frequency band" may correspond to the LC region. Thus, for the synthesis of the link, we can use a lossless MTL model.

Consequently, we can use:

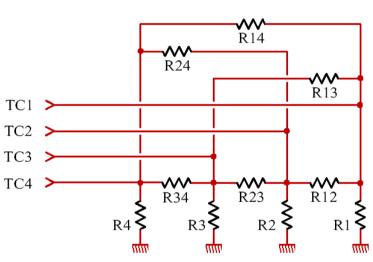
• a termination circuit made of n(n + 1)/2 resistors, as shown here for n = 4;

◆ TX circuits and RX circuits performing real and frequency-independent linear combinations.

□ Outside the known frequency band, the MTL model used for the synthesis of the link is not required to be an accurate model of the actual interconnection.

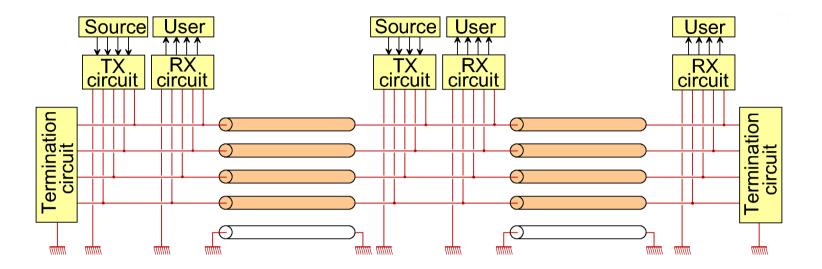
□ Of course, for the analysis of the link, we should use an MTL model providing accurate predictions in the whole frequency band used for transmission. This accurate model could include losses and departures from the assumption of uniformity.

Seminar 32 — Tutorial on Echo and Crosstalk in Printed Circuit Boards and Multi-Chip Modules — Lecture Slides









□ A link implementing the ZXtalk method can be point-to-point or multidrop. Above: a bus using parallel connection for the TX circuits and RX circuits.

□ Each mode of a point-to-point link implementing the ZXtalk method can be used for simplex, half duplex or full duplex transmission.

Each mode of a multidrop link implementing the ZXtalk method can be used for simplex transmission or as a bus.



### ☐ There are 8 possible designs, corresponding to the following equations

Interface	Connection	Design using modal voltages (voltage-mode signaling)	Design using modal currents (current-mode signaling)
TX circuit	series (low impedance)	$\mathbf{v}_T = \pm a  \mathbf{S}  \mathrm{diag}_n(\boldsymbol{\alpha}_1, \dots, \boldsymbol{\alpha}_n)  \mathbf{x}_I$	$\mathbf{v}_T = a  \mathbf{Z}_C \mathbf{T} \operatorname{diag}_n(\lambda_1, \dots, \lambda_n) \mathbf{x}_I$
	parallel (high impedance)	$\mathbf{i}_T = a \mathbf{Z}_C^{-1} \mathbf{S} \operatorname{diag}_n(\alpha_1, \dots, \alpha_n) \mathbf{x}_I$	$\mathbf{i}_T = \pm a \mathbf{T} \operatorname{diag}_n(\lambda_1, \dots, \lambda_n) \mathbf{x}_I$
RX circuit	series (low impedance)	$\mathbf{x}_{O} = \pm \operatorname{diag}_{n}(\boldsymbol{\beta}_{1}, \dots, \boldsymbol{\beta}_{n})\mathbf{S}^{-1}\mathbf{Z}_{C}\mathbf{i}_{R}$	$\mathbf{x}_{O} = \operatorname{diag}_{n}(\boldsymbol{\mu}_{1}, \dots, \boldsymbol{\mu}_{n})\mathbf{T}^{-1}\mathbf{i}_{R}$
	parallel (high impedance)	$\mathbf{x}_{O} = \operatorname{diag}_{n}(\boldsymbol{\beta}_{1}, \dots, \boldsymbol{\beta}_{n})\mathbf{S}^{-1}\mathbf{v}_{R}$	$\mathbf{x}_{O} = \pm \operatorname{diag}_{n}(\boldsymbol{\mu}_{1}, \dots, \boldsymbol{\mu}_{n})\mathbf{T}^{-1}\mathbf{Z}_{C}^{-1}\mathbf{v}_{R}$
			(87)

where  $\mathbf{x}_{I}$ ,  $\mathbf{v}_{T}$  and  $\mathbf{i}_{T}$  are the column-vectors of the input signals, output voltages and output currents of the TX circuit, respectively, a is the number of termination circuits;  $\mathbf{v}_{R}$ ,  $\mathbf{i}_{R}$  and  $\mathbf{x}_{O}$  are the column-vectors of the input voltages, input currents and output signals of the RX circuit, respectively; the  $\alpha_{i}$ ,  $\lambda_{i}$ ,  $\beta_{i}$ , and the  $\mu_{i}$  are arbitrary nonzero constants.



 $\square$  Between a TX circuit and a RX circuit connected to the interconnection at  $z_{TX}$  and  $z_{RX}$ , respectively, we have, in the known frequency band:

$$x_{Oi} = \alpha_i \beta_i e^{-\gamma_i |z_{RX} - z_{TX}|} x_{Ii}$$
 or  $x_{Oi} = \lambda_i \mu_i e^{-\gamma_i |z_{RX} - z_{TX}|} x_{Ii}$  (88)

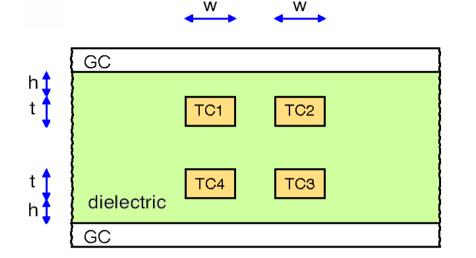
according to the case.

□ It can be shown that voltage-mode signaling and current mode signaling are equivalent when generalized associated eigenvectors are used.

☐ The general ZXtalk method reduces echo and internal crosstalk, but it does not reduce external crosstalk

□ For  $n \ge 3$ , a termination circuit can often use less than n(n + 1)/2 resistors, for instance only 2n - 1 resistors.

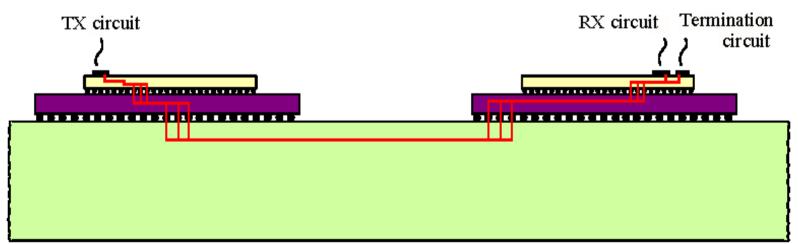
 $\Box$  However, the general ZXtalk method is mostly appropriate for small values of *n*, because the complexity of the TX and RX circuits increases as  $n^2$ .





☐ The ZXtalk method can easily be applied to a differential pair, and to the 4-TC configuration shown [82].

□ It is possible to extend the general ZXtalk method to some interconnections which cannot be modeled with a uniform MTL. This extension is useful when one wishes to consider an interconnection spanning several substrates, such as shown below.





□ The basic ideas of this extension are the following [76]:

• we assume that the interconnection can be modeled as a non-uniform MTL, so that, at each point *z* we can formally define **S**, **T** and **Z**<sub>*C*</sub> using (23) and (28);

• we can require that S and  $Z_c$  are independent of z, a result which can easily be obtained in several important types of interconnections;

• we can then define  $\mathbf{v}_M$  and  $\mathbf{i}_M$  with (24), and show that they satisfy

$$\begin{cases} \frac{d^2 \mathbf{v}_M}{dz^2} - \Gamma^2 \mathbf{v}_M = \frac{d \Gamma}{dz} \Gamma^{-1} \frac{d \mathbf{v}_M}{dz} \\ \frac{d^2 \mathbf{i}_M}{dz^2} - \Gamma^2 \mathbf{i}_M = \frac{d \Gamma}{dz} \Gamma^{-1} \frac{d \mathbf{i}_M}{dz} \end{cases}$$
(89)

•  $\Gamma_G$  and  $d\Gamma_G/dz$  being diagonal matrices, these equations are decoupled, so that we have achieved a modal decomposition applicable to the non-uniform MTL.

Suggested reading relating or relevant to modal signaling [9] [13] [19] [27] [28]
 [35] [36] [37] [38] [42] [54] [55] [66] [76] [79] [82] [84].



# 15. Modal signaling in a degenerate interconnection

 $\Box$  By definition, a completely degenerate interconnection (CDI) is such that  $\gamma_1, ..., \gamma_n$ , may be regarded as equal, in a given frequency band. This for instance occurs when losses are negligible and the propagation medium is homogeneous, but we won't need these assumptions [11].

 $\Box$  In the given frequency band, (23) defining T and S becomes

$$\begin{cases} \mathbf{T}^{-1}\mathbf{Y'Z'T} = \gamma^2 \mathbf{1}_n \\ \mathbf{S}^{-1}\mathbf{Z'Y'S} = \gamma^2 \mathbf{1}_n \end{cases}$$
(90)

where  $\gamma$  is the common value of the propagation constants. In (90) the eigenvalues are completely degenerate. We have :

$$\mathbf{Y'Z'} = \mathbf{Z'Y'} = \gamma^2 \mathbf{1}_n \tag{91}$$

Thus, **S** and/or **T** may be chosen equal to  $\mathbf{1}_n$ , so that

$$\mathbf{Z}_{C} = \frac{1}{\gamma} \, \mathbf{Z}' = \gamma \, \mathbf{Y}'^{-1} \tag{92}$$



 $\square$  A general definition of the special ZXtalk method for CDI [29] relates to an *m*-channel link such that:

♦ the interconnection has *n* TCs, with  $n \ge m$ , and may be modeled, with a sufficient accuracy, in a known frequency band, as a uniform (n + 1)-conductor MTL such that the propagation constants of the different propagation modes may be considered as substantially equal;

• the interconnection is connected at at least one end to a termination circuit having, in the known frequency band, an impedance matrix near  $Z_C$ ;

◆ a TX circuit delivers natural electrical variables, each natural electrical variable being mainly determined by one and only one input signal;

◆ a RX circuit delivers output signals, each of the output signals being mainly determined by one and only one of said natural electrical variables.

**The special ZXtalk method for CDI corresponds to a particular implementation of the general ZXtalk method, in which S or T are chosen equal to \mathbf{1}\_n.** 



### ☐ There are 8 possible designs, corresponding to the following equations

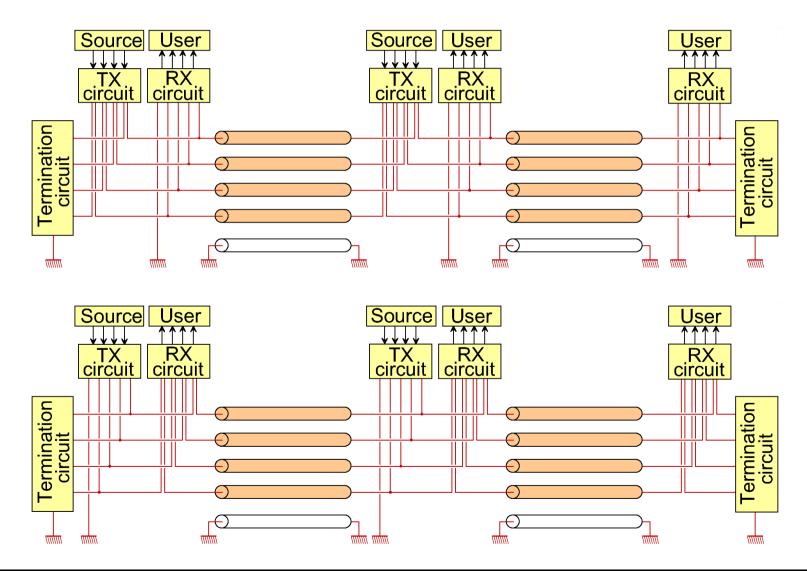
Interface	Connection	Design using modal voltages (voltage-mode signaling)	Design using modal currents (current-mode signaling)
TX circuit	series (low impedance)	$\mathbf{v}_T = \pm a \operatorname{diag}_n(\alpha_1, \dots, \alpha_n) \mathbf{x}_I$	$\mathbf{v}_T = a  \mathbf{Z}_C  \operatorname{diag}_n(\lambda_1, \dots, \lambda_n)  \mathbf{x}_I$
	parallel (high impedance)	$\mathbf{i}_T = a \mathbf{Z}_C^{-1} \operatorname{diag}_n(\boldsymbol{\alpha}_1, \dots, \boldsymbol{\alpha}_n) \mathbf{x}_I$	$\mathbf{i}_T = \pm a \operatorname{diag}_n(\lambda_1, \dots, \lambda_n) \mathbf{x}_I$
RX circuit	series (low impedance)	$\mathbf{x}_{O} = \pm \operatorname{diag}_{n}(\boldsymbol{\beta}_{1}, \dots, \boldsymbol{\beta}_{n}) \mathbf{Z}_{C} \mathbf{i}_{R}$	$\mathbf{x}_{O} = \operatorname{diag}_{n}(\boldsymbol{\mu}_{1}, \dots, \boldsymbol{\mu}_{n})\mathbf{i}_{R}$
	parallel (high impedance)	$\mathbf{x}_{O} = \operatorname{diag}_{n}(\boldsymbol{\beta}_{1}, \dots, \boldsymbol{\beta}_{n})\mathbf{v}_{R}$	$\mathbf{x}_{O} = \pm \operatorname{diag}_{n}(\boldsymbol{\mu}_{1}, \dots, \boldsymbol{\mu}_{n}) \mathbf{Z}_{C}^{-1} \mathbf{v}_{R}$
			(02)

(93)

where  $\mathbf{x}_I$ ,  $\mathbf{v}_T$  and  $\mathbf{i}_T$  are the column-vectors of the input signals, output voltages and output currents of the TX circuit, respectively, a is the number of termination circuits;  $\mathbf{v}_R$ ,  $\mathbf{i}_R$  and  $\mathbf{x}_O$  are the column-vectors of the input voltages, input currents and output signals of the RX circuit, respectively; the  $\alpha_i$ ,  $\lambda_i$ ,  $\beta_i$ , and the  $\mu_i$  are arbitrary nonzero constants.



#### **T**wo designs do not require linear combinations:

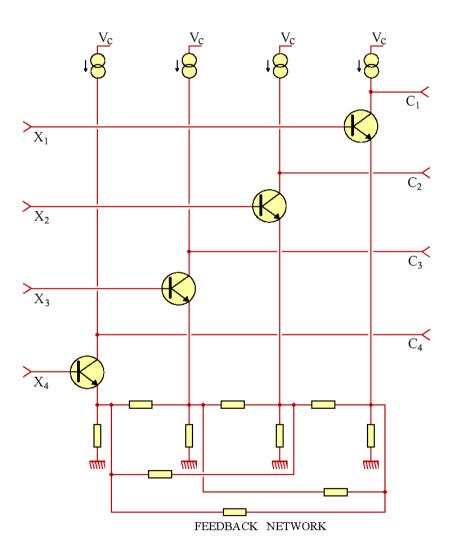




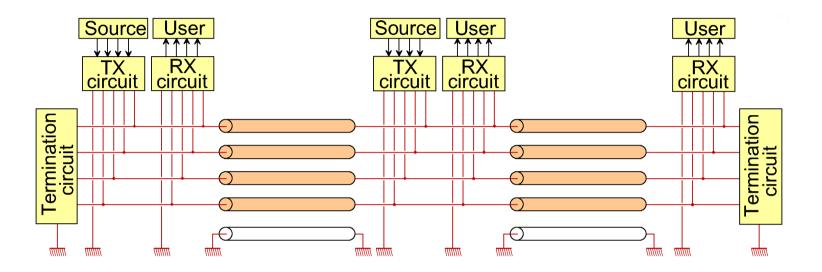
 $\Box$  In the designs shown above, the remaining difficulty is the floating TX circuits or RX circuits, connected in series with the interconnection.

□ This difficulty is circumvented using a MIMO series-series feedback amplifier (MIMO-SSFA) that can be used to perform all linear combinations containing  $\mathbf{Z}_{C}^{-1}$  in the previous table, in a wide bandwidth.

Structure of a simple 4-channel MIMO-SSFA using bipolar transistors →







 $\Box$  A design using a MIMO-SSFA in each TX circuit may have the TX circuits and RX circuits connected in parallel with the interconnection.

 $\Box$  It is often to possible to design such a link so that the number of circuit elements in the termination circuits and TX circuits is proportional to *n* when *n* is large [43].

☐ Thus, this method is appropriate for reducing echo and internal crosstalk in the widest bandwidth, and it is applicable to massively parallel interconnections.



□ We have seen that the FEXT is small, to the first order in the weak coupling approximation, in a single-ended link using a CDI and pseudo-matched impedances at the ends of each TC. Thus, the special ZXtalk method for CDI is mostly of interest in cases where:

◆ there is a strong coupling between the TCs; and/or

◆ the interconnection is used for bidirectional transmission.

□ Like the general ZXtalk method, the special ZXtalk method for CDI can be extended to some interconnections which cannot be modeled with a uniform MTL.

Suggested reading relating or relevant to the special ZXtalk method for CDI [29]
 [32] [33] [34] [37] [38] [40] [42] [43] [50] [52] [72] [75] [76] [82] [85] [86].



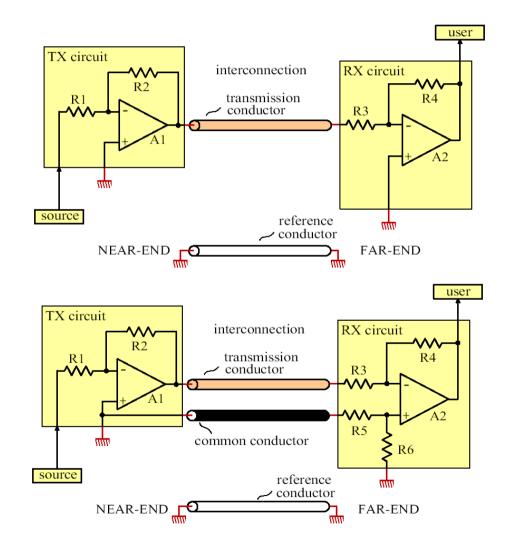
### 16. Pseudo-differential links

□ A single-ended link is subject to external crosstalk with other circuits on the same chip, MCM or PCB.

□ A simple pseudo-differential link (PDL) is protected against crosstalk using little additional hardware.

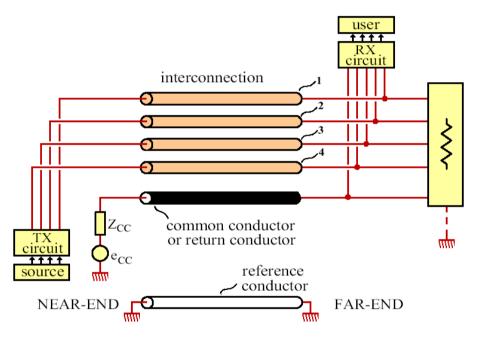
□ A PDL providing *m* channels uses only m + 1 conductors to reduce external crosstalk in *m* channels.

☐ There are four possible PDL architectures.





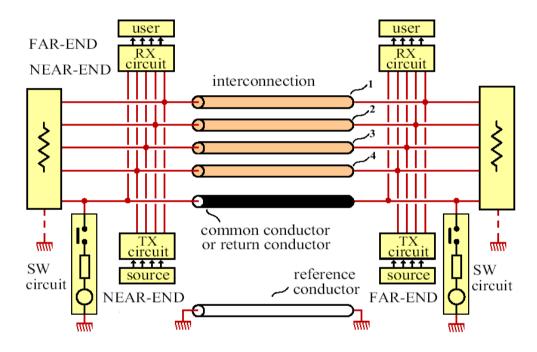
☐ First architecture: a unidirectional PDL with voltage-driven common conductor (VDCC). The common conductor (CC) may be used as a return conductor (RC).



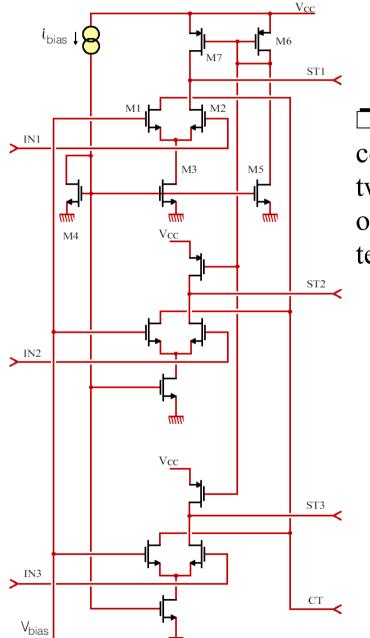
- ◆ The termination circuit may or may not be present.
- ◆ The TX circuit may be a conventional line driver (but this is not necessary).
- ◆ This VDCC architecture cannot be used in a bidirectional PDL.



☐ Second architecture: a bidirectional PDL may be built using common terminal switching circuits (SW circuits).

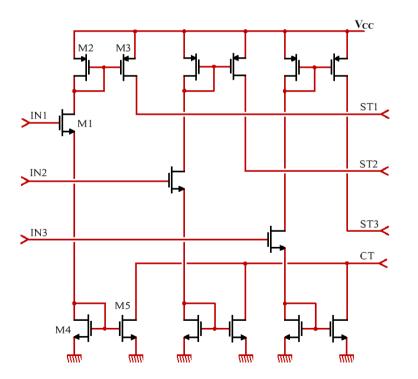


- One or more of the termination circuits may or may not be present.
- ◆ The TX circuits may be conventional 3-state line drivers.
- ◆ This SW circuit architecture cannot be used for full duplex operation.



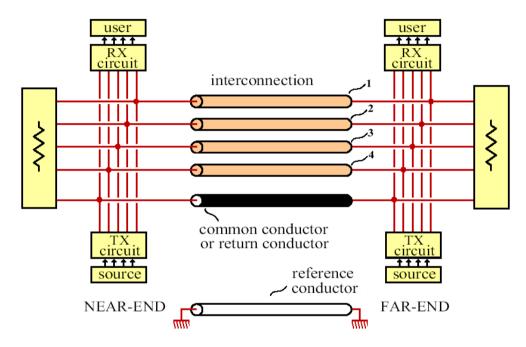


**D** PDLs may also use TX circuits producing a constant (or zero) common-mode current, such as the two 3-channels TX circuits shown here. The ST*n* output terminal is coupled to the TC*n*. The CT output terminal is coupled to the RC.





# Using such TX circuits, we can introduce constant common-mode current (CCMC) architectures



- ◆ A least one floating termination circuit is needed.
- ◆ A unidirectional CCMC architecture is possible (third architecture).

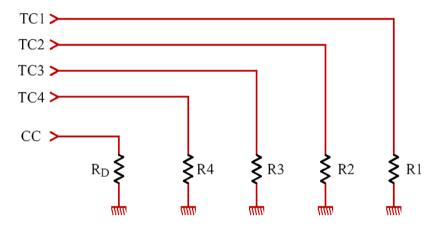
◆ A bidirectional CCMC architecture is compatible with full duplex signaling (fourth architecture).



□ We can define four types of termination circuit.

**Type 0: no termination.** 

☐ Type 1: termination circuit typically made of impedors connected to the GC or to a power supply node.

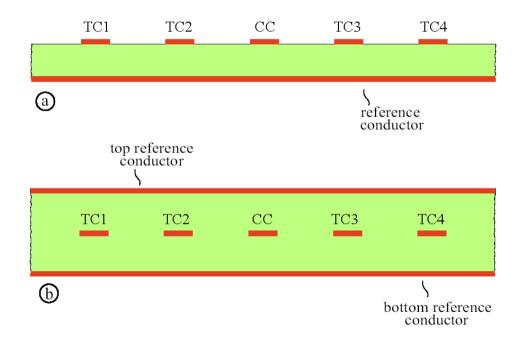


♦ Operates as intended only if the electric and magnetic fields of the signals are mainly located between the TCs and the GC.

- ◆ The GC belongs to the signal path: this is a problem.
- ◆ Not compatible with the CCMC architecture.

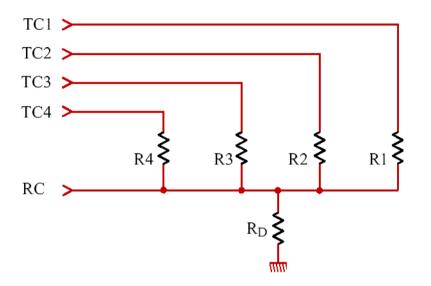


**D** Example of 2 interconnection-ground structures compatible with type 1 termination circuits:





□ Type 2: floating termination circuit made of impedors connected between a TC and the RC.

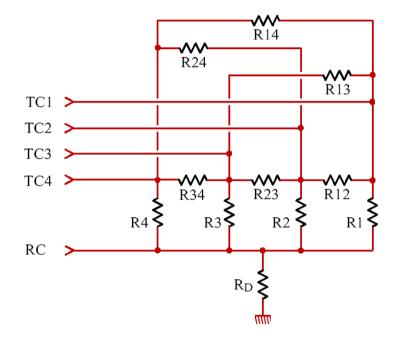


♦ Operates as intended only if the electric and magnetic fields of the signals are mainly located between the TCs and the RC.

- ◆ Does not degrade the reduction of external crosstalk.
- ◆ Compatible with the CCMC architecture.



□ Type 3: floating termination circuit comprising impedors connected between a TC and the RC and impedors connected between two TCs.



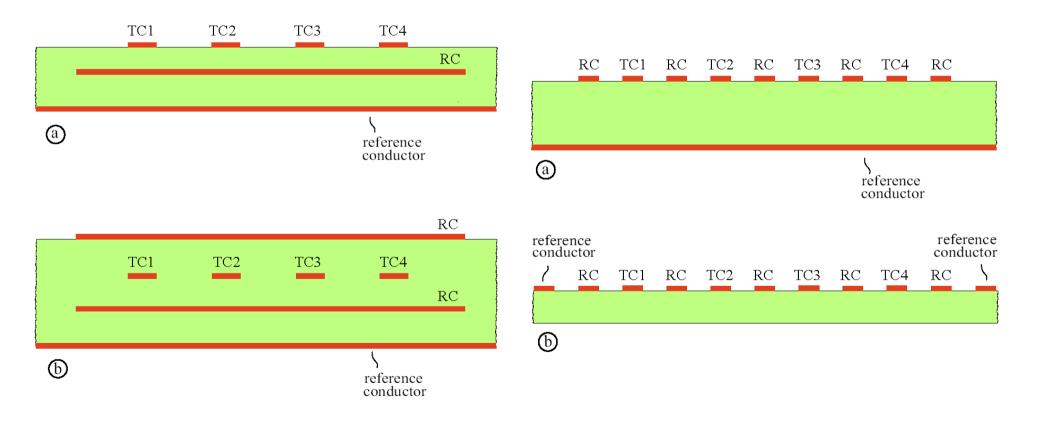
• Operates as intended only if the requirement for the second type is met and a variation of the ZXtalk method is used to reduce internal crosstalk.

• External crosstalk and internal crosstalk can be effectively reduced.

◆ Compatible with the CCMC architecture.



# □ Example of 4 interconnection-ground structures compatible with floating (i.e. type 2 or type 3) termination circuits:





**This type of interconnection may be modeled as a** (n + 2)-conductor MTL, this MTL using natural voltages referenced to ground and natural currents as variables.

 $\Box$  For such a model, we use, at a given abscissa *z* along the interconnection:

- for any integer  $\alpha$  such that  $1 \le \alpha \le n$ , the natural current  $i_{\alpha}$ ;
- the current flowing in the RC, denoted by  $i_{n+1}$ ;

• for any integer  $\alpha$  such that  $1 \le \alpha \le n$ , the voltage between the TC number  $\alpha$  and the GC, denoted by  $v_{G\alpha}$ ;

• the voltage between the RC and the GC, denoted by  $v_{Gn+1}$ .

□ Later, we will also need:

• the common-mode current  $i_{CM} = i_1 + ... + i_{n+1}$ ;

• for any integer  $\alpha$  such that  $1 \le \alpha \le n$ , the voltage between the TC number  $\alpha$  and the RC, denoted by  $v_{R\alpha}$  and given by  $v_{R\alpha} = v_{G\alpha} - v_{Gn+1}$ .



 $\Box$  For the (*n* + 2)-conductor MTL model, the telegrapher's equations are:

$$\begin{cases} \frac{d \mathbf{v}_G}{dz} = -\mathbf{Z}'_G \mathbf{i}_G \\ \frac{d \mathbf{i}_G}{dz} = -\mathbf{Y}'_G \mathbf{v}_G \end{cases}$$
(94)

where

 $\mathbf{v}_{G}$  is the column-vector of the natural voltages referenced to ground, the entries of which are  $v_{G1}, ..., v_{Gn+1}$ ;

 $\mathbf{i}_{G}$  is the column-vector of the natural currents, the entries of which are  $i_{G1}, \dots, i_{Gn+1}$ ;

 $\mathbf{Z'}_G$  is the p.u.l. impedance matrix with respect to ground;

 $\mathbf{Y}'_{G}$  is the p.u.l. admittance matrix with respect to ground.

 $\Box \mathbf{Z'}_G$  and  $\mathbf{Y'}_G$  are symmetric matrices of size  $(n + 1) \times (n + 1)$ .



□ The interconnection can also be described by an equivalent set of equations [78]:

$$\begin{cases} \frac{d \mathbf{v}_{R}}{dz} = -\mathbf{Z}_{R}' \mathbf{i}_{R} + i_{MC} \mathbf{Z}_{E}' \\ \frac{d \mathbf{i}_{R}}{dz} = -\mathbf{Y}_{R}' \mathbf{v}_{R} - v_{Gn+1} \mathbf{Y}_{E}' \end{cases} \quad \text{and} \quad \begin{cases} \frac{d \mathbf{v}_{Gn+1}}{dz} = {}^{t} \mathbf{Z}_{E}' \mathbf{i}_{R} - i_{MC} \mathbf{Z}_{EE}' \\ \frac{d \mathbf{i}_{MC}}{dz} = -{}^{t} \mathbf{Y}_{E}' \mathbf{v}_{R} - v_{Gn+1} \mathbf{Y}_{EE}' \end{cases}$$
(95)

where

 $\mathbf{v}_R$  is the column-vector of the natural voltages referenced to the RC, the entries of which are  $v_{R1}, \dots, v_{Rn}$ ;

 $\mathbf{i}_R$  is the column-vector of the natural currents  $i_1, \dots, i_n$ ;  $\mathbf{Z'}_R$  is the p.u.l. impedance matrix with respect to the RC, of size  $n \times n$ ;  $\mathbf{Y'}_R$  is the p.u.l. admittance matrix with respect to the RC, of size  $n \times n$ ;  $\mathbf{Z'}_E$  is the p.u.l. transfer impedance vector, of size  $n \times 1$ ;  $\mathbf{Y'}_E$  is the p.u.l. transfer admittance vector, of size  $n \times 1$ ;  $\mathbf{Z'}_{EE}$  is the p.u.l. external circuit impedance; and  $\mathbf{Y'}_{EE}$  is the p.u.l. external circuit admittance.



 $\Box$  If the RC behaves as a good electromagnetic screen, norms of  $\mathbf{Z}'_E$  and  $\mathbf{Y}'_E$  are small, so that we may use the following approximation

$$\begin{cases} \frac{d \mathbf{v}_R}{dz} \approx -\mathbf{Z}'_R \mathbf{i}_R \\ \frac{d \mathbf{i}_R}{dz} \approx -\mathbf{Y}'_R \mathbf{v}_R \end{cases}$$
(96)

and

$$\begin{cases} \frac{d v_{Gn+1}}{dz} \approx -i_{MC} Z'_{EE} \\ \frac{d i_{MC}}{dz} \approx -v_{Gn+1} Y'_{EE} \end{cases}$$
(97)

 $\square$  By (96), the propagation of signals in the interconnection may be modeled as a propagation in a (n + 1)-conductor MTL.



☐ The *ZXnoise method* is the combination of a floating termination circuit (type 2 or type 3 termination circuit) and an appropriate interconnection-ground structure [48] [61] [62] [77].

 $\Box$  The interconnection is proportioned such that all conductors other than the *n* TCs and the RC may be neglected when one models propagation in the interconnection, at the design stage.

 $\Box$  More precisely, the design stage involves the assumption that the interconnection may be modeled with a sufficient accuracy as a (n + 1)-conductor MTL.

□ This assumption leads to a floating termination circuit.

 $\Box$  A more accurate analysis of course requires a (n + 2)-conductor MTL model.

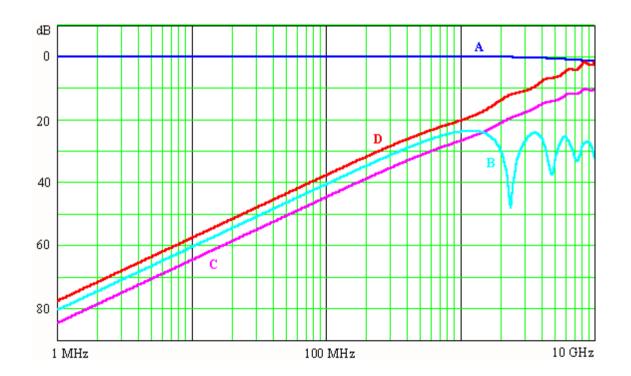
□ If a type 3 termination circuit is used, the designer combines the ZXnoise and ZXtalk methods.



Example 1: a compact 4-channel 0.03-m long PDL using single-ended line drivers, a RC grounded at the near-end (VDCC) and type 2 termination circuits.

The TCs are very close to each other, so that internal crosstalk is relatively high. However, echo is low and a good rejection of external crosstalk is obtained.

Attenuation of transmitted signal when TC1 is excited: curve A. NEXT loss on TC2 when TC1 is excited: curve B. FEXT loss on TC2 when TC1 is excited: curve C. Far-end external crosstalk loss on TC1 for ground bounce in the TX circuit: curve D. Note that the far-end external crosstalk loss would be 0 dB for single-ended links !

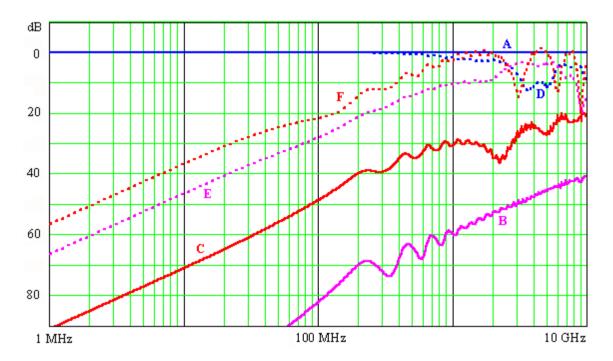




□ Example 2: Two compact 4-channel 0.3-m long PDLs using the same interconnection-ground structure, single-ended line drivers and VDCC.

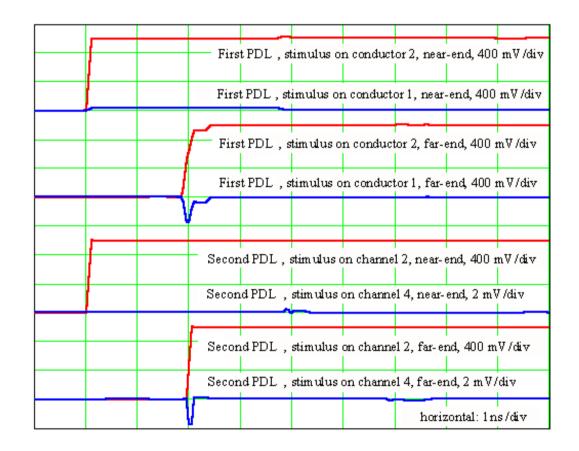
The First PDL uses a type 2 termination circuit (ZXnoise method). The Second PLD is a ZXnoise + ZXtalk design (using a type 3 termination circuit).

When a type 3 termination circuit is used, in channel 2: attenuation of transmitted signal (curve A), lowest FEXT loss when channel 3 or 4 are excited (curve B), attenuation of ground bounce (curve C). When a type 2 termination circuit is used, in TC2: attenuation of transmitted signal (curve D), lowest FEXT loss (curve E), attenuation of ground bounce (curve F).





Time domain voltages in the PDL, measured on conductor 2 in the case of a type 2 termination circuit (First PDL) or on channel 2 in the case of a type 3 termination circuit (Second PDL), the stimulus being a 1V step having a 100 ps rise time. In the first PDL, conductor 1 is the one that produces the highest peak crosstalk voltage on conductor 2. In the second PDL, channel 4 is the one that produces the highest peak crosstalk voltage on channel 2.





□ From the presentation of pseudo-differential signaling, we see that:

• pseudo-differential signaling effectively reduces external crosstalk using m + 1 conductors instead of 2m conductors for m differential links;

◆ the ZXnoise method effectively reduces external crosstalk and echo;

◆ the ZXnoise + ZXtalk combination also effectively reduces internal crosstalk.

☐ There are 12 pseudo-differential transmission schemes corresponding to the compatible combinations of an architecture and a type of termination circuit.

Termination		Architecture	of the PDL	
circuit	VDCC (unidirectional)	SW circuit (bidirectional)	Unidirectional CCMC	Bidirectional CCMC
Type 0	Prior Art	New		
Type 1	Prior Art	New		
Type 2 (ZXnoise)	New	New	New	New
Type 3 (ZXnoise)	New	New	New	New



□ Several authors have introduced other multichannel transmission schemes, in which one or more of the output signals of the RX circuit are mainly determined by the voltages between two TCs, sometimes with the addition of a code maintaining a constant current [25] [44] [67] [68] [71] [73].

D Even though some such transmission schemes are sometimes referred to as pseudo-differential, they have not been considered in this presentation.

Suggested reading on pseudo-differential signaling [18] [23] [24] [26] [31] [39]
 [41] [45] [46] [47] [48] [53] [56] [57] [58] [59] [60] [61] [62] [63] [64] [65] [69] [70]
 [72] [74] [77] [78] [83].



# Appendix: Inventions of Excem quoted in this tutorial

# **Cross-reference**:

Internal No. Reference Internal No. Reference Internal No. Reference	Internal No.	Reference
P26[27]P36[46]P41[58]P27[28]P37[47]P42[59]P28[29]P38[48]P43[61]P30[40]P39[56]P44[62]P35[45]P40[57]P45[69]	P46 P47 P48 P49	[70] [76] [77] [81]

## □ Inventions on the ZXtalk method (essential inventions in red):

ZVtally math ad	L	ink				
ZXtalk method	Not pseudo-differential	Pseudo-differential (ZXnoise + ZXtalk)				
General	P26, P27, P47, P39, P40, P42	<b>P39</b> , <b>P40</b> , <b>P43</b> , <b>P48</b> , P42, P45, P46				
Special for CDI	P28, P47 P30, P33, P36, P39, P40, P41, P42	<b>P39</b> , <b>P40</b> , <b>P44</b> , <b>P48</b> P30, P33, P36, P41, P42, P45, P46				



## □ Inventions on pseudo-differential signaling (essential inventions in red):

Termination	Architecture of the PDL								
circuit	VDCC	SW circuit	Unidirectional	Bidirectional					
	(unidirectional)	(bidirectional)	CCMC	CCMC					
Type 0	Prior Art P39, P46	<mark>P37</mark> P39, P46							
Type 1	Prior Art P39, P46	<mark>P37</mark> P39, P46							
Type 2	<mark>P35, P38, P48</mark>	<b>P35, P37, P38, P48</b>	<b>P35</b> , <b>P36</b> , <b>P38</b> , <b>P48</b>						
(ZXnoise)	P39, P41, P46	P39, P41, P46	P39, P41, P42, P46						
Type 3	<b>P39</b> , <b>P40</b> , <b>P43</b> , <b>P44</b> , <b>P48</b>	P39, P40, P43, P44, P45		<b>42</b> , <b>P43</b> , <b>P44</b> , <b>P48</b>					
(ZXnoise+ZXtalk)	P30, P33, P41, P46	P48, P30, P33, P41, P46		P41, P46					



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# Annexes

Worksheet A: Computation of the eigenvectors and the characteristic impedance matrix of a first interconnection

pages A-1 to A-8

Worksheet B: Computation of the eigenvectors and the characteristic impedance matrix of a second interconnection

pages B-1 to B-8

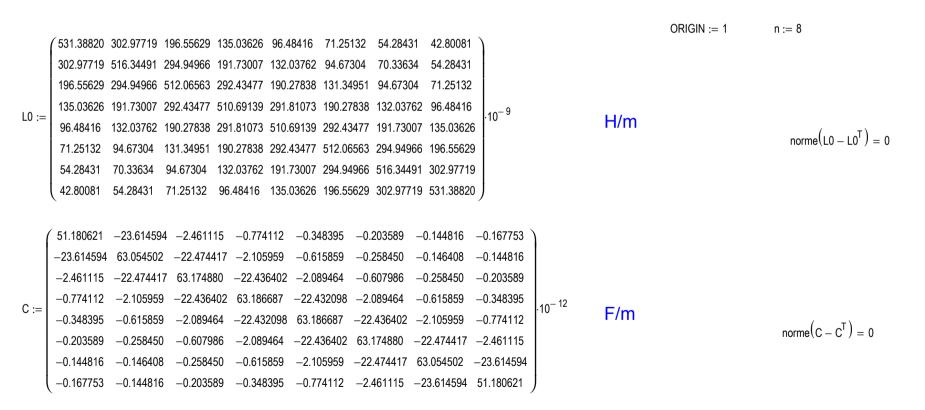
## Computation of the eigenvectors and the characteristic impedance matrix

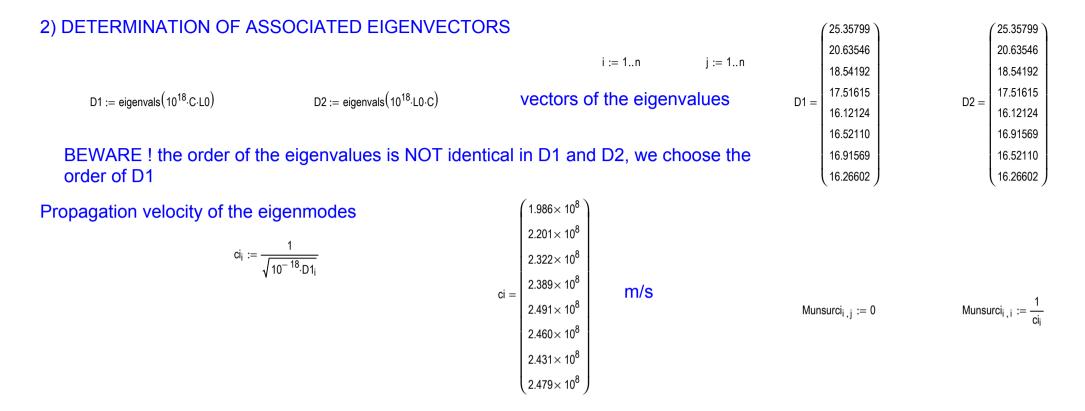
Authors: Frédéric Broydé and Evelyne Clavelier. Prepared with Mathcad 2000 professional (Mathcad is a registered trademark of its owner). date: 21 Oct. 2010 © Excem 2010

File: Worksheet A of Tutorial v2a.mcd

#### 1) DEFINITION OF THE MULTICONDUCTOR TRANSMISSION LINE PARAMETERS

#### (we use some data of Worksheet F of Sem 33 Chap 2 v2a.mcd)





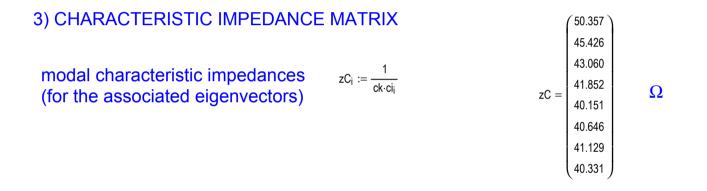
Definition of the change of variables for the currents, i.e. transition matrix from modal currents to natural currents (matrix T)

$$T_{i,j} := (eigenvec(10^{18} \cdot C \cdot L0, D1_j))_i$$

$$T = \begin{pmatrix} 0.41534 & -0.54029 & -0.50948 & -0.44297 & 0.10052 & 0.28765 & -0.36808 & -0.19704 \\ 0.32623 & -0.37448 & -0.18359 & 0.09610 & -0.27671 & -0.48644 & 0.35047 & 0.45949 \\ 0.32954 & -0.24578 & 0.17435 & 0.47288 & 0.41565 & 0.10000 & 0.34421 & -0.46202 \\ 0.33537 & -0.08629 & 0.41992 & -0.26632 & -0.49047 & 0.41308 & -0.35102 & 0.19128 \\ 0.32954 & 0.24578 & 0.17435 & -0.47288 & -0.41565 & -0.10000 & 0.34421 & -0.46202 \\ 0.32954 & 0.24578 & 0.17435 & -0.47288 & -0.41565 & -0.10000 & 0.34421 & -0.46202 \\ 0.32954 & 0.24578 & 0.17435 & -0.47288 & -0.41565 & -0.10000 & 0.34421 & -0.46202 \\ 0.32954 & 0.24578 & 0.17435 & -0.47288 & -0.41565 & -0.10000 & 0.34421 & -0.46202 \\ 0.32954 & 0.24578 & 0.17435 & -0.47288 & -0.41565 & -0.10000 & 0.34421 & -0.46202 \\ 0.32623 & 0.37448 & -0.18359 & -0.09610 & 0.27671 & 0.48644 & 0.35047 & 0.45949 \\ 0.41534 & 0.54029 & -0.50948 & 0.44297 & -0.10052 & -0.28765 & -0.36808 & -0.19704 \\ 0.41534 & 0.54029 & -0.50948 & 0.44297 & -0.10052 & -0.28765 & -0.36808 & -0.19704 \\ 0.41534 & 0.54029 & -0.50948 & 0.44297 & -0.10052 & -0.28765 & -0.36808 & -0.19704 \\ 0.41534 & 0.54029 & -0.50948 & 0.44297 & -0.10052 & -0.28765 & -0.36808 & -0.19704 \\ 0.41534 & 0.54029 & -0.50948 & 0.44297 & -0.10052 & -0.28765 & -0.36808 & -0.19704 \\ 0.41534 & 0.54029 & -0.50948 & 0.44297 & -0.10052 & -0.28765 & -0.36808 & -0.19704 \\ 0.41534 & 0.54029 & -0.50948 & 0.44297 & -0.10052 & -0.28765 & -0.36808 & -0.19704 \\ 0.41534 & 0.54029 & -0.50948 & 0.44297 & -0.10052 & -0.28765 & -0.36808 & -0.19704 \\ 0.41534 & 0.54029 & -0.50948 & 0.44297 & -0.10052 & -0.28765 & -0.36808 & -0.19704 \\ 0.41534 & 0.54029 & -0.50948 & 0.44297 & -0.10052 & -0.28765 & -0.36808 & -0.19704 \\ 0.41534 & 0.54029 & -0.50948 & 0.44297 & -0.10052 & -0.28765 & -0.36808 & -0.19704 \\ 0.4154 & 0.54029 & -0.50948 & 0.44297 & -0.10052 & -0.28765 & -0.36808 & -0.19704 \\ 0.4154 & 0.54029 & -0.50948 & 0.44297 & -0.10052 & -0.28765 & -0.36808 & -0.19704 \\ 0.4154 & 0.54029 & -0.50948 & 0.44297 & -0.10052$$

Definition of the change of variables for the voltages, i.e. transition matrix from modal voltages to natural voltages (matrix S)

$ck := 10^{-10}$	arbitrary constant		2.054301	-1.895924	-1.155304	-0.702251	0.083579	0.290674	-0.444683	-0.174771
$S := ck \cdot C^{-1} \cdot T$			2.274451	-1.724031	-0.462953	0.247219	-0.275695	-0.609739	0.559119	0.498559
$S := CK \cdot C \rightarrow I$			2.414446	-1.187700	0.576552	0.976135	0.405178	0.114345	0.532082	-0.483689
		S =	2.484387	-0.422463	1.314582	0.543835	-0.480948	0.500468	-0.515995	0.206748
		5 –	2.484387	0.422463	1.314582	-0.543835	0.480948	-0.500468	-0.515995	0.206748
			2.414446	1.187700	0.576552	-0.976135	-0.405178	-0.114345	0.532082	-0.483689
			2.274451	1.724031	-0.462953	-0.247219	0.275695	0.609739	0.559119	0.498559
			2.054301	1.895924	-1.155304	0.702251	-0.083579	-0.290674	-0.444683	-0.174771



modal characteristic impedance matrix	Zmc := diag(zC)										
			(116.390	61.099	37.310	24.238	16.431	11.564	8.446	6.438	
			61.099	113.169	59.453	36.347	23.653	16.084	11.390	8.446	
			37.310	59.453	112.326	58.969	36.072	23.525	16.084	11.564	
characteristic impedance matrix	$Zc := S \cdot Zmc \cdot T^{-1}$	Zc =	24.238	36.347	58.969	112.066	58.852	36.072	23.653	16.431	
characteristic impedance matrix	20 3.200	$2c := 5.2mc \cdot 1$ $2c = \begin{bmatrix} 16.431 & 23.653 & 36.072 & 58.852 & 112.066 & 58.969 \\ 11.564 & 16.084 & 23.525 & 36.072 & 58.969 & 112.326 \end{bmatrix}$	36.347	24.238	Ω						
			112.326	59.453	37.310						
			8.446	11.390	16.084	23.653	36.347	59.453	113.169	61.099	
			6.438	8.446	11.564	16.431	24.238	37.310	61.099	116.390	)

#### control of the equations for computing the characteristic impedance matrix:

$$S \cdot Munsurci T \cdot S^{-1} \cdot L0 = \begin{bmatrix} 116.390 & 61.099 & 37.310 & 24.238 & 16.431 & 11.564 & 8.446 & 6.438 \\ 61.099 & 113.169 & 59.453 & 36.347 & 23.653 & 16.084 & 11.390 & 8.446 \\ 37.310 & 59.453 & 112.326 & 59.869 & 36.072 & 23.525 & 16.084 & 11.564 \\ 24.238 & 36.347 & 58.969 & 112.06 & 58.852 & 36.072 & 23.525 & 16.084 & 11.564 \\ 16.431 & 23.653 & 36.072 & 58.852 & 112.06 & 58.969 & 36.347 & 24.238 \\ 11.564 & 16.084 & 23.525 & 36.072 & 58.852 & 112.06 & 58.969 & 36.347 & 24.238 \\ 11.564 & 16.084 & 23.525 & 36.072 & 58.852 & 112.06 & 58.969 & 36.347 & 24.238 \\ 11.564 & 16.084 & 23.525 & 36.072 & 58.852 & 112.06 & 58.969 & 36.347 & 24.238 \\ 11.564 & 16.084 & 23.525 & 36.072 & 58.852 & 112.06 & 58.969 & 36.347 & 24.238 \\ 11.564 & 16.084 & 23.525 & 36.072 & 58.969 & 112.326 & 59.453 & 37.310 \\ 8.446 & 11.390 & 16.084 & 23.653 & 36.347 & 59.453 & 113.169 & 61.099 \\ 6.438 & 8.446 & 11.564 & 16.431 & 24.238 & 37.310 & 61.099 & 116.390 \\ \end{bmatrix}$$

$$L0 \cdot T \cdot Munsurci T \cdot T = \begin{bmatrix} 116.390 & 61.099 & 37.310 & 24.238 & 16.431 & 11.564 & 8.446 & 6.438 \\ 61.09 & 113.169 & 59.453 & 36.347 & 59.453 & 113.169 & 61.099 \\ 6.438 & 8.446 & 11.564 & 16.431 & 24.238 & 37.310 & 61.099 & 116.390 \\ \end{bmatrix}$$

$$L0 \cdot T \cdot Munsurci T \cdot T = \begin{bmatrix} 116.390 & 61.099 & 37.310 & 24.238 & 16.431 & 11.564 & 8.446 & 6.438 \\ 61.09 & 113.169 & 59.453 & 36.347 & 59.453 & 113.169 & 61.099 \\ 6.438 & 8.446 & 11.564 & 16.431 & 24.238 & 37.310 & 61.099 & 116.390 \\ \end{bmatrix}$$

$$L0 \cdot T \cdot Munsurci T \cdot T = \begin{bmatrix} 116.390 & 61.099 & 37.310 & 24.238 & 16.431 & 11.564 & 8.446 & 6.438 \\ 61.09 & 113.169 & 59.453 & 36.347 & 23.55 & 36.047 & 23.55 & 36.047 & 23.55 & 36.047 & 23.55 & 36.047 & 23.55 & 36.04 & 11.390 & 8.446 \\ 11.390 & 16.084 & 23.55 & 36.072 & 23.55 & 16.084 & 11.564 & 16.431 & 24.238 & 37.310 & 8.466 & 37.310 & 59.453 & 31.236 & 59.453 & 37.310 & 8.466 & 37.310 & 59.453 & 31.236 & 59.453 & 37.310 & 8.466 & 37.310 & 59.453 & 31.236 & 59.453 & 37.310 & 8.466 & 37.310 & 59.453 & 36.347 & 59.453 & 110.64 & 11.564 & 6.438 & 21.564 & 6.438 & 21.564 & 11.564 & 16.431 & 24.238 & 36.347 & 59.453$$

4) MATCHED LOADS  

$$Zc^{-1} = \begin{pmatrix} 0.012 & -6.073 \times 10^{-3} & -6.123 \times 10^{-4} & -2.154 \times 10^{-4} & -1.085 \times 10^{-4} & -6.856 \times 10^{-5} & -5.111 \times 10^{-5} & -6.325 \times 10^{-5} \\ -6.073 \times 10^{-3} & 0.015 & -5.767 \times 10^{-3} & -5.064 \times 10^{-4} & -1.629 \times 10^{-4} & -7.643 \times 10^{-5} & -4.724 \times 10^{-5} & -5.111 \times 10^{-5} \\ -6.073 \times 10^{-3} & 0.015 & -5.767 \times 10^{-3} & -5.011 \times 10^{-4} & -1.629 \times 10^{-4} & -7.643 \times 10^{-5} & -6.856 \times 10^{-5} \\ -6.123 \times 10^{-4} & -5.064 \times 10^{-4} & -5.756 \times 10^{-3} & 0.015 & -5.754 \times 10^{-3} & -5.011 \times 10^{-4} & -1.629 \times 10^{-4} & -2.154 \times 10^{-4} & -2.154$$

S

Values of the resistances of a network of resistors having an impedance matrix equal to Zc, presented as a matrix (the diagonal entries are the values of the grounded resistors).

 $164.674 = 1.633 \times 10^3 4.643 \times 10^3 9.215 \times 10^3 1.459 \times 10^4 1.956 \times 10^4 1.581 \times 10^4$ 205.831  $1.975 \times 10^{3}$   $6.140 \times 10^{3}$   $1.308 \times 10^{4}$   $2.117 \times 10^{4}$   $1.956 \times 10^{4}$ 164.674 373.546 173.403 173.740 1.996  $\times$  10<sup>3</sup> 6.243  $\times$  10<sup>3</sup> 1.308  $\times$  10<sup>4</sup> 1.459  $\times$  10<sup>4</sup>  $1.633 \times 10^{3}$ 173.403 407.954  $4.643 \times 10^3$   $1.975 \times 10^3$  173.740 173.784  $1.996 \times 10^3$   $6.140 \times 10^3$   $9.215 \times 10^3$ 418.071 R = 173.740  $1.975 \times 10^3$   $4.643 \times 10^3$  $9.215 \times 10^{3}$   $6.140 \times 10^{3}$   $1.996 \times 10^{3}$  173.784 418.071  $1.459 \times 10^4$   $1.308 \times 10^4$   $6.243 \times 10^3$   $1.996 \times 10^3$  173.740 407.954 173.403  $1.633 \times 10^3$  $1.956 \times 10^4$   $2.117 \times 10^4$   $1.308 \times 10^4$   $6.140 \times 10^3$   $1.975 \times 10^3$  173.403373.546 164.674  $1.581 \times 10^4$   $1.956 \times 10^4$   $1.459 \times 10^4$   $9.215 \times 10^3$   $4.643 \times 10^3$   $1.633 \times 10^3$ 164.674 205.831

#### 5) ORTHOGONALITY OF ASSOCIATED EIGENVECTORS

 $S \cdot S^{\mathsf{T}} = \begin{pmatrix} 9.962 & 7.766 & 5.775 & 4.303 & 3.254 & 2.508 & 1.977 & 1.604 \\ 7.766 & 9.430 & 7.388 & 5.547 & 4.166 & 3.173 & 2.467 & 1.977 \\ 5.775 & 7.388 & 9.220 & 7.277 & 5.487 & 4.138 & 3.173 & 2.508 \\ 4.303 & 5.547 & 7.277 & 9.165 & 7.253 & 5.487 & 4.166 & 3.254 \\ 3.254 & 4.166 & 5.487 & 7.253 & 9.165 & 7.277 & 5.547 & 4.303 \\ 2.508 & 3.173 & 4.138 & 5.487 & 7.277 & 9.220 & 7.388 & 5.775 \\ 1.977 & 2.467 & 3.173 & 4.166 & 5.547 & 7.388 & 9.430 & 7.766 \\ 1.604 & 1.977 & 2.508 & 3.254 & 4.303 & 5.775 & 7.766 & 9.962 \end{pmatrix}$ 

1	( 1.1874	0.0015	0.0063	0.0150	0.0187	0.0185	0.0175	0.0254
	0.0015	0.9368	-0.0423	0.0150 -0.0101	0.0045	0.0100	0.0114	0.0175
	0.0063	-0.0423	0.9377	-0.0409	-0.0101	0.0041	0.0100	0.0185
T.T <sup>T</sup> =								
1.1 -	0.0187	0.0045	-0.0101	0.9382 -0.0410	0.9382	-0.0409	-0.0101	0.0150
	0.0185	0.0100	0.0041	-0.0101	-0.0409	0.9377	-0.0423	0.0063
	0.0175	0.0114	0.0100	0.0045	-0.0101	-0.0423	0.9368	0.0015
	0.0254	0.0175	0.0185	0.0187	0.0150	0.0063	0.0015	1.1874

Thus, the column-vectors of S (eigen-voltages) are not orthogonal, and the column-vectors of T (eigen-currents) are not orthogonal.

Ω

#### 6) MODAL INDUCTANCE MATRIX AND MODAL CAPACITANCE MATRIX, FOR ASSOCIATED EIGENVECTORS

 $Cm := T^{-1} \cdot C \cdot S$ 

 $Lm := S^{-1} \cdot L0 \cdot T$ 

10 <sup>9</sup> Lm =	$ \begin{pmatrix} 253.580 & 4.144 \times 10^{-14} & -1.425 \times 10^{-14} & -1.868 \times 10^{-14} & 1.865 \times 10^{-15} & -9.632 \times 10^{-15} & 2.558 \times 10^{-14} & 206.355 & -2.740 \times 10^{-15} & -1.724 \times 10^{-14} & 6.420 \times 10^{-15} & 1.527 \times 10^{-14} & 1.5558 \times 10^{-14} & 2.882 \times 10^{-15} & 185.419 & -2.416 \times 10^{-14} & -5.492 \times 10^{-15} & -4.199 \times 10^{-15} & 7.5558 \times 10^{-14} & 7.063 \times 10^{-15} & -3.810 \times 10^{-15} & 175.161 & 2.113 \times 10^{-14} & 5.256 \times 10^{-15} & 1.527 \times 10^{-14} & 1.5023 \times 10^{-14} & -5.549 \times 10^{-15} & 1.588 \times 10^{-14} & 1.786 \times 10^{-14} & 161.212 & 3.096 \times 10^{-14} & 2.5023 \times 10^{-14} & -7.112 \times 10^{-15} & -7.566 \times 10^{-15} & 1.637 \times 10^{-15} & 9.008 \times 10^{-15} & 1.65.211 & 3.567 \times 10^{-14} & 1.087 \times 10^{-14} & 2.054 \times 10^{-14} & -1.762 \times 10^{-14} & -1.087 \times 10^{-15} & 1.020 \times 10^{-14} & -5.079 \times 10^{-14} & 3.738 \times 10^{-14} & -2.568 \times 10^{-14} & -1.411 \times 10^{-14} & 1.052 \times 10^{-14} & 2.797 \times 10^{-14} & 3.588 \times 10^{-14} & -1.411 \times 10^{-14} & 1.052 \times 10^{-14} & 2.577 \times 10^{-14} & 3.578 \times 10^{-14} & -5.578 \times 10^{-14} & -1.411 \times 10^{-14} & 1.572 \times 10^{-14} & 3.578 \times 10^{-14} & 3.578 \times 10^{-14} & -5.578 \times 10^{-14} & -1.411 \times 10^{-14} & 1.572 \times 10^{-14} & 3.578 \times 10^{-14} & 3.578 \times 10^{-14} & -1.411 \times 10^{-14} & 1.572 \times 10^{-14} & 3.578 \times 10^{-14} & 3.578 \times 10^{-14} & -1.411 \times 10^{-14} & 1.572 \times 10^{-14} & 3.578 \times 10^{-14} & 3.578 \times 10^{-14} & -1.411 \times 10^{-14} & 1.572 \times 10^{-14} & 3.578 \times 10^{-14} & 3.578 \times 10^{-14} & -1.411 \times 10^{-14} & 1.572 \times 10^{-14} & 3.578 \times 10^{-14} & 3.578 \times 10^{-14} & -1.411 \times 10^{-14} & 1.572 \times 10^{-14} & 3.578 \times 10^{-14} & 3.578 \times 10^{-14} & -1.411 \times 10^{-14} & 1.572 \times 10^{-14} & 3.578 \times 10$	$.767 \times 10^{-15}  3.2$ $.819 \times 10^{-15}  -1.3$ $.709 \times 10^{-15}  4.1$ $.227 \times 10^{-14}  4.1$ $.187 \times 10^{-14}  1.5$ 169.157  1.7	$21 \times 10^{-15}$ $985 \times 10^{-14}$ $10 \times 10^{-15}$ $56 \times 10^{-15}$	nH/m
10 <sup>12</sup> ·Cm =	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	$\begin{array}{rrrr} .195 \times 10^{-15} & 1.5 \\ .636 \times 10^{-15} & 1.13 \\ 185 \times 10^{-15} & -9.1 \\ 846 \times 10^{-15} & -1.6 \\ .786 \times 10^{-15} & -1.3 \\ 100 & 5.9 \end{array}$	$54 \times 10^{-16}$ $53 \times 10^{-14}$ $26 \times 10^{-15}$ $016 \times 10^{-14}$	pF/m
		100         0         0         0           0         100         0         0           0         0         100         0           0         0         100         0           0         0         0         100           0         0         0         0         0           0         0         0         0         0           0         0         0         0         0           0         0         0         0         0           0         0         0         0         0           0         0         0         0         0	100 0 0	

#### 7) MODAL CHARACTERISTIC IMPEDANCE MATRIX, FOR BIORTHONORMAL EIGENVECTORS

 $\mathsf{Zmc} := \mathsf{diag}(\mathsf{ci}){\cdot}\mathsf{T}^\mathsf{T}{\cdot}\mathsf{L0}{\cdot}\mathsf{T}$ 

$$Zmc = \begin{pmatrix} 324.707 & 1.600 \times 10^{-14} & 2.132 \times 10^{-14} & 4.545 \times 10^{-16} & -1.662 \times 10^{-14} & -1.006 \times 10^{-16} & 4.386 \times 10^{-14} & 4.533 \times 10^{-15} \\ 2.935 \times 10^{-14} & 181.553 & -1.962 \times 10^{-14} & -4.343 \times 10^{-14} & 1.242 \times 10^{-14} & 3.046 \times 10^{-14} & 5.426 \times 10^{-15} & -1.509 \times 10^{-15} \\ 1.950 \times 10^{-14} & -2.335 \times 10^{-14} & 114.207 & -3.102 \times 10^{-14} & -8.240 \times 10^{-18} & -2.320 \times 10^{-15} & 1.004 \times 10^{-14} & -4.305 \times 10^{-14} \\ -2.021 \times 10^{-14} & -4.805 \times 10^{-14} & -2.759 \times 10^{-14} & 78.788 & 1.016 \times 10^{-14} & 2.057 \times 10^{-15} & 3.634 \times 10^{-16} & 5.609 \times 10^{-15} \\ -2.125 \times 10^{-14} & 1.213 \times 10^{-14} & 1.395 \times 10^{-15} & 9.188 \times 10^{-15} & 39.267 & 2.394 \times 10^{-14} & 5.023 \times 10^{-15} & -2.359 \times 10^{-14} \\ -1.211 \times 10^{-15} & 2.854 \times 10^{-14} & -2.963 \times 10^{-15} & 1.894 \times 10^{-15} & 2.408 \times 10^{-14} & 48.644 & 5.093 \times 10^{-15} & 2.283 \times 10^{-14} \\ 5.125 \times 10^{-14} & 9.272 \times 10^{-16} & 8.773 \times 10^{-15} & 2.068 \times 10^{-15} & 2.918 \times 10^{-15} & 3.946 \times 10^{-15} & 59.546 & 1.262 \times 10^{-14} \\ 3.545 \times 10^{-15} & -1.064 \times 10^{-15} & -4.801 \times 10^{-14} & 2.408 \times 10^{-15} & -2.332 \times 10^{-14} & 1.275 \times 10^{-14} & 42.472 \end{pmatrix}$$

In this example, Zmc is a diagonal matrix, within the accuracy of our computation. We note that Zmc is different in section 3 and in section 7.

#### 8) MODAL INDUCTANCE MATRIX AND MODAL CAPACITANCE MATRIX, FOR BIORTHONORMAL EIGENVECTORS

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$$Lm := T^{T} \cdot L0 \cdot T \qquad Cm := T^{-1} \cdot C \cdot (T^{-1})^{T}$$

$$1.635 \times 10^{3} \qquad 1.381 \times 10^{-13} \qquad 1.073 \times 10^{-13} \qquad -3.588 \times 10^{-14} \qquad -1.217 \times 10^{-13} \qquad -4.291 \times 10^{-15} \qquad 1.756 \times 10^{-13} \qquad 1.886 \times 10^{-14} \qquad 1.886 \times 10^{-14} \qquad 1.886 \times 10^{-14} \qquad 1.659 \times 10^{-13} \qquad -1.839 \times 10^{-14} \qquad 2.617 \times 10^{-15} \qquad 1.044 \times 10^{-13} \qquad -7.941 \times 10^{-14} \qquad 491.780 \qquad -1.048 \times 10^{-13} \qquad -1.650 \times 10^{-14} \qquad -7.290 \times 10^{-15} \qquad 5.081 \times 10^{-14} \qquad -2.023 \times 10^{-13} \qquad 1.640 \times 10^{-14} \qquad -9.223 \times 10^{-14} \qquad -1.998 \times 10^{-13} \qquad -1.172 \times 10^{-13} \qquad 329.746 \qquad 4.044 \times 10^{-14} \qquad 5.477 \times 10^{-15} \qquad 1.965 \times 10^{-15} \qquad 1.640 \times 10^{-14} \qquad -9.223 \times 10^{-14} \qquad 5.066 \times 10^{-14} \qquad 7.593 \times 10^{-17} \qquad 3.546 \times 10^{-14} \qquad 157.663 \qquad 9.741 \times 10^{-14} \qquad 1.459 \times 10^{-14} \qquad -8.741 \times 10^{-14} \qquad -8.327 \times 10^{-15} \qquad 1.405 \times 10^{-13} \qquad -1.665 \times 10^{-14} \qquad 9.787 \times 10^{-14} \qquad 197.718 \qquad 2.192 \times 10^{-14} \qquad 8.884 \times 10^{-14} \qquad 2.212 \times 10^{-13} \qquad 2.003 \times 10^{-16} \qquad 3.467 \times 10^{-15} \qquad 2.408 \times 10^{-14} \qquad 1.398 \times 10^{-14} \qquad 2.41906 \qquad 5.1111 \times 10^{-14} \qquad 1.510 \times 10^{-14} \qquad -6.921 \times 10^{-15} \qquad -1.934 \times 10^{-13} \qquad 1.474 \times 10^{-14} \qquad -9.384 \times 10^{-14} \qquad 8.847 \times 10^{-14} \qquad 4.211 \times 10^{-14} \qquad 171.293 \qquad$$

$$10^{12} \cdot Cm = \begin{pmatrix} 15.508 & -3.295 \times 10^{-15} & -4.422 \times 10^{-16} & -3.410 \times 10^{-15} & 3.831 \times 10^{-17} & 7.541 \times 10^{-15} & -2.624 \times 10^{-15} & 3.093 \times 10^{-15} \\ -3.701 \times 10^{-15} & 25.021 & 2.773 \times 10^{-15} & 1.177 \times 10^{-14} & -8.526 \times 10^{-15} & -9.900 \times 10^{-15} & -4.224 \times 10^{-16} & -1.647 \times 10^{-16} \\ -6.409 \times 10^{-16} & 1.892 \times 10^{-15} & 37.704 & 1.144 \times 10^{-14} & 1.904 \times 10^{-15} & 6.926 \times 10^{-15} & -8.489 \times 10^{-15} & 4.172 \times 10^{-14} \\ -2.699 \times 10^{-15} & 1.063 \times 10^{-14} & 1.169 \times 10^{-14} & 53.120 & -4.637 \times 10^{-15} & -3.911 \times 10^{-15} & 6.848 \times 10^{-15} & -1.407 \times 10^{-14} \\ -1.347 \times 10^{-15} & -9.571 \times 10^{-15} & 1.539 \times 10^{-15} & -5.944 \times 10^{-15} & 102.251 & -5.048 \times 10^{-14} & -3.976 \times 10^{-15} & 4.703 \times 10^{-14} \\ 8.307 \times 10^{-15} & -9.552 \times 10^{-15} & 8.964 \times 10^{-15} & -4.823 \times 10^{-16} & -4.906 \times 10^{-14} & 83.559 & -5.401 \times 10^{-15} & -4.648 \times 10^{-14} \\ -2.580 \times 10^{-15} & -1.466 \times 10^{-15} & -8.872 \times 10^{-15} & 7.046 \times 10^{-15} & -4.360 \times 10^{-16} & -4.062 \times 10^{-15} & 69.070 & -1.454 \times 10^{-14} \\ 8.539 \times 10^{-16} & 3.708 \times 10^{-16} & 4.264 \times 10^{-14} & -1.471 \times 10^{-14} & 4.269 \times 10^{-14} & -4.578 \times 10^{-14} & -1.673 \times 10^{-14} & 94.960 \end{pmatrix}$$

In this example, Lm and Cm are diagonal matrices, within the accuracy of our computation. We note that Lm and Cm are different in section 6 and in section 8.

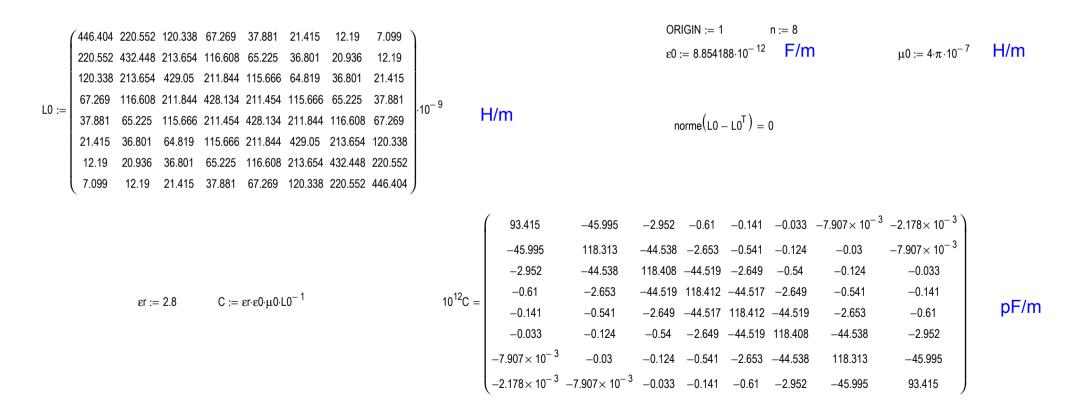
## Computation of the eigenvectors and the characteristic impedance matrix

Authors: Frédéric Broydé and Evelyne Clavelier. Prepared with Mathcad 2000 professional (Mathcad is a registered trademark of its owner). date: 21 Oct. 2010 © Excem 2010

File: Worksheet B of Tutorial v2a.mcd

#### 1) DEFINITION OF THE MULTICONDUCTOR TRANSMISSION LINE PARAMETERS

#### (we use some data of Worksheet N of Sem 33 Chap 2 v2a.mcd)



#### 2) DETERMINATION OF ASSOCIATED EIGENVECTORS

i := 1..n i := 1..n In this worksheet, we use the a priori knowledge concerning completely degenerate interconnections.  $D1_i := \epsilon r \cdot \epsilon 0 \cdot \mu 0$  $1.792 \times 10^{8}$ Propagation velocity of the eigenmodes  $1.792 \times 10^{8}$  $ci_i := \frac{1}{\sqrt{D1_i}}$  $1.792 \times 10^{8}$  $1.792 \times 10^{8}$ m/s ci =  $1.792 \times 10^{8}$ Munsurci<sub>i,i</sub> := .  $Munsurci_{i,j} := 0$ 1.792×10<sup>8</sup>  $1.792 \times 10^{8}$  $1.792 \times 10^{8}$ 

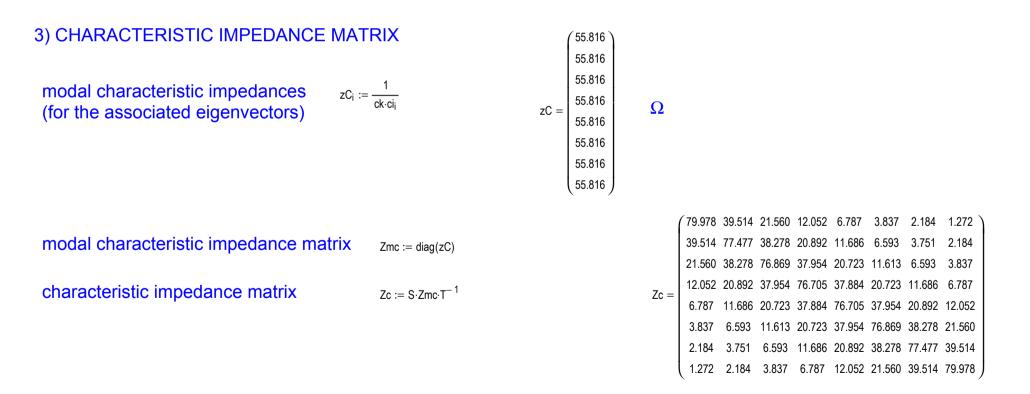
Definition of the change of variables for the currents, i.e. transition matrix from modal currents to natural currents (matrix T)

Here, we can use T := identity(n)

1.00000 0.00000 0.00000 0.00000 0.00000 0.00000 0.00000 0.00000 0.00000 1.00000 0.00000 0.00000 0.00000 0.00000 0.00000 0.00000 0.00000 1.00000 0.00000 0.00000 0.00000 0.00000 0.00000 0.00000 0.00000 0.00000 1.00000 0.00000 0.00000 0.00000 0.00000 T = 0.00000 0.00000 0.00000 1.00000 0.00000 0.00000 0.00000 0.00000 0.00000 0.00000 0.00000 1.00000 0.00000 0.00000 0.00000 0.00000 0.00000 0.00000 0.00000 1.00000 0.00000 0.00000 0.00000 0.00000 0.00000 0.00000 0.00000 1.00000

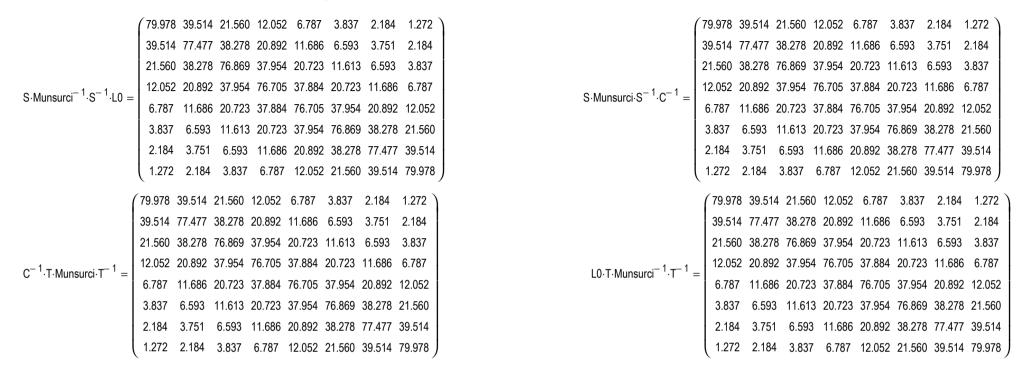
#### Definition of the change of variables for the voltages, i.e. transition matrix from modal voltages to natural voltages (matrix S)

$ck := 10^{-10}$	arbitrary constant	(	1.432885	0.707937	0.386266	0.215923	0.121592	0.068739	0.039128	0.022787
$ck := 10^{-10}$ S := ck·C <sup>-1</sup> ·T			0.707937	1.388089	0.685795	0.374293	0.209362	0.118125	0.067201	0.039128
			0.386266	0.685795	1.377182	0.679985	0.371269	0.208059	0.118125	0.068739
		S =		0.374293						
		3 –	0.121592	0.209362	0.371269	0.678733	1.374242	0.679985	0.374293	0.215923
			0.068739	0.118125	0.208059	0.371269	0.679985	1.377182	0.685795	0.386266
			0.039128	0.067201	0.118125	0.209362	0.374293	0.685795	1.388089	0.707937
		l	0.022787	0.039128	0.068739	0.121592	0.215923	0.386266	0.707937	1.432885



Ω

#### control of the equations for computing the characteristic impedance matrix:



#### 4) MATCHED LOADS

4) MATCHED LOADS  

$$z_{c}^{-1} = \begin{pmatrix} 0.017 & -8.241 \times 10^{-3} & -5.288 \times 10^{-4} & -1.093 \times 10^{-4} & -2.518 \times 10^{-5} & -5.943 \times 10^{-6} & -1.417 \times 10^{-6} & -3.902 \times 10^{-7} \\ -8.241 \times 10^{-3} & 0.021 & -7.979 \times 10^{-3} & -4.754 \times 10^{-4} & -9.696 \times 10^{-5} & -2.225 \times 10^{-5} & -5.309 \times 10^{-6} & -1.417 \times 10^{-6} \\ -5.288 \times 10^{-4} & -7.979 \times 10^{-3} & 0.021 & -7.976 \times 10^{-3} & -4.746 \times 10^{-4} & -9.680 \times 10^{-5} & -2.225 \times 10^{-5} & -5.943 \times 10^{-6} \\ -1.093 \times 10^{-4} & -4.754 \times 10^{-4} & -7.976 \times 10^{-3} & 0.021 & -7.976 \times 10^{-3} & -4.746 \times 10^{-4} & -9.696 \times 10^{-5} & -2.518 \times 10^{-5} \\ -2.518 \times 10^{-5} & -9.696 \times 10^{-5} & -4.746 \times 10^{-4} & -7.976 \times 10^{-3} & 0.021 & -7.976 \times 10^{-3} & -4.746 \times 10^{-4} & -9.696 \times 10^{-5} & -2.518 \times 10^{-4} \\ -5.943 \times 10^{-6} & -2.225 \times 10^{-5} & -9.680 \times 10^{-5} & -4.746 \times 10^{-4} & -7.976 \times 10^{-3} & 0.021 & -7.979 \times 10^{-3} & -5.288 \times 10^{-4} \\ -5.943 \times 10^{-6} & -2.225 \times 10^{-5} & -9.696 \times 10^{-5} & -4.746 \times 10^{-4} & -7.979 \times 10^{-3} & 0.021 & -7.979 \times 10^{-3} & -5.288 \times 10^{-4} \\ -5.943 \times 10^{-6} & -2.225 \times 10^{-5} & -9.696 \times 10^{-5} & -4.746 \times 10^{-4} & -7.979 \times 10^{-3} & 0.021 & -7.979 \times 10^{-3} & -5.288 \times 10^{-4} \\ -1.417 \times 10^{-6} & -5.309 \times 10^{-6} & -2.225 \times 10^{-5} & -9.696 \times 10^{-5} & -4.754 \times 10^{-4} & -7.979 \times 10^{-3} & 0.021 & -8.241 \times 10^{-3} \\ -3.902 \times 10^{-7} & -1.417 \times 10^{-6} & -5.943 \times 10^{-6} & -2.518 \times 10^{-5} & -1.093 \times 10^{-4} & -5.288 \times 10^{-4} & -8.241 \times 10^{-3} & 0.017 \end{pmatrix}$$

S

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Values of the resistances of a network of resistors having an impedance matrix equal to Zc, presented as a matrix (the diagonal entries are the values of the grounded resistors).

	127.799	121.351	$1.891 \times 10^3$	$9.152\!\times 10^3$	$3.972  imes 10^4$	$1.683  imes 10^5$	$7.059\!\times 10^5$	$2.563 \times 10^6$	
	121.351	228.535	125.322	$2.104\!\times 10^3$	$1.031  imes 10^4$	$4.493  imes 10^4$	$1.884\!\times 10^5$	7.059×10 <sup>5</sup>	
			242.123						
R =	$9.152 \times 10^{3}$ $3.972 \times 10^{4}$	$2.104\!\times 10^3$	125.377	245.005	125.380	$2.107  imes 10^3$	$1.031 \times 10^4$	3.972×10 <sup>4</sup>	
N –	$3.972  imes 10^4$	$1.031 \times 10^4$	$2.107  imes 10^3$	125.380	245.005	125.377	$2.104\!\times10^3$	9.152×10 <sup>3</sup>	
	$1.683  imes 10^{5}$	$4.493\!\times 10^4$	$1.033  imes 10^4$	$2.107\!\times 10^3$	125.377	242.123	125.322	1.891×10 <sup>3</sup>	
	$7.059  imes 10^5$	$1.884\!\times 10^5$	$4.493\!\times 10^4$	$1.031 \times 10^4$	$2.104\!\times 10^3$	125.322	228.535	121.351	
	2.563×10 <sup>6</sup>	$7.059\!\times 10^5$	$1.683  imes 10^5$	$3.972  imes 10^4$	$9.152  imes 10^3$	$1.891 \times 10^3$	121.351	127.799	

#### 5) ORTHOGONALITY OF ASSOCIATED EIGENVECTORS

 $S \cdot S^{\mathsf{T}} = \begin{pmatrix} 2.772 & 2.380 & 1.783 & 1.253 & 0.846 & 0.556 & 0.358 & 0.226 \\ 2.380 & 3.102 & 2.537 & 1.858 & 1.287 & 0.861 & 0.561 & 0.358 \\ 1.783 & 2.537 & 3.178 & 2.573 & 1.874 & 1.293 & 0.861 & 0.556 \\ 1.253 & 1.858 & 2.573 & 3.195 & 2.580 & 1.874 & 1.287 & 0.846 \\ 0.846 & 1.287 & 1.874 & 2.580 & 3.195 & 2.573 & 1.858 & 1.253 \\ 0.556 & 0.861 & 1.293 & 1.874 & 2.573 & 3.178 & 2.537 & 1.783 \\ 0.358 & 0.561 & 0.861 & 1.287 & 1.858 & 2.537 & 3.102 & 2.380 \\ 0.226 & 0.358 & 0.556 & 0.846 & 1.253 & 1.783 & 2.380 & 2.772 \end{pmatrix}$ 

 $T \cdot T^{T} = \begin{pmatrix} 1.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 1.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 1.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 1.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 1.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 1.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 1.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 1.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 1.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 1.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 & 0.0000 \\ 0.000$ 

Thus, the column-vectors of S (eigen-voltages) are not orthogonal, but the column-vectors of T (eigen-currents) are orthogonal.

Ω

#### 6) MODAL INDUCTANCE MATRIX AND MODAL CAPACITANCE MATRIX, FOR ASSOCIATED EIGENVECTORS

 $Cm := T^{-1} \cdot C \cdot S$ 

 $Lm := S^{-1} \cdot L0 \cdot T$ 

10 <sup>9</sup> Lm =	$ = \begin{pmatrix} 311.542 & -3.139 \times 10^{-14} & -1.777 \times 10^{-14} & -1.614 \times 10^{-14} & -2.104 \times 10^{-15} & -7.114 \times 10^{-15} & -2.852 \times 10^{-15} & -2.331 \times 10^{-15} \\ -1.478 \times 10^{-14} & 311.542 & -4.832 \times 10^{-14} & -3.299 \times 10^{-15} & -7.094 \times 10^{-15} & -6.145 \times 10^{-15} & -1.917 \times 10^{-15} & 1.262 \times 10^{-15} \\ -2.636 \times 10^{-14} & -3.212 \times 10^{-14} & 311.542 & -6.829 \times 10^{-15} & -1.030 \times 10^{-14} & 9.968 \times 10^{-17} & 1.243 \times 10^{-15} & -1.027 \times 10^{-15} \\ -1.031 \times 10^{-14} & -7.195 \times 10^{-15} & -2.901 \times 10^{-14} & 311.542 & -2.227 \times 10^{-14} & -1.029 \times 10^{-14} & -8.843 \times 10^{-15} & -1.596 \times 10^{-14} \\ 5.078 \times 10^{-15} & -1.065 \times 10^{-14} & 7.759 \times 10^{-15} & 1.607 \times 10^{-14} & 311.542 & -6.588 \times 10^{-15} & 3.888 \times 10^{-15} & 3.115 \times 10^{-14} \\ 9.722 \times 10^{-15} & 1.581 \times 10^{-14} & 3.657 \times 10^{-14} & 4.203 \times 10^{-14} & 1.199 \times 10^{-14} & 311.542 & 6.764 \times 10^{-14} & 1.356 \times 10^{-14} \\ -8.609 \times 10^{-15} & -1.310 \times 10^{-14} & -2.748 \times 10^{-14} & -3.632 \times 10^{-14} & -6.019 \times 10^{-14} & -1.816 \times 10^{-13} & 311.542 & -1.231 \times 10^{-13} \\ 4.160 \times 10^{-17} & 1.414 \times 10^{-16} & 2.730 \times 10^{-15} & -1.049 \times 10^{-14} & 5.616 \times 10^{-15} & -5.125 \times 10^{-15} & 1.092 \times 10^{-14} & 311.542 \end{pmatrix}$	nH/m
10 <sup>12</sup> ·Cm =		pF/m
	ted, Lm and Cm are diagonal matrices, accuracy of our computation. Here Cm is $10^{12} \text{ck-identity}(n) = \begin{pmatrix} 100 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 100 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 &$	pF/m

#### 7) MODAL CHARACTERISTIC IMPEDANCE MATRIX, FOR BIORTHONORMAL EIGENVECTORS

 $Zmc := diag(ci) \cdot T^T \cdot L0 \cdot T$ 

	(79.978	39.514	21.560	12.052	6.787	3.837	2.184	1.272
	39.514	77.477	38.278	20.892	11.686	6.593	3.751	2.184
	21.560	38.278	76.869	37.954	20.723	11.613	6.593	3.837
Zmc =	12.052	20.892	37.954	76.705	37.884	20.723	11.686	6.787
	6.787	11.686	20.723	37.884	76.705	37.954	20.892	12.052
	3.837	6.593	11.613	20.723	37.954	76.869	38.278	21.560
	2.184	3.751	6.593	11.686	20.892	38.278	77.477	39.514
	1.272	2.184	3.837	6.787	12.052	21.560	39.514	79.978

Ω

In this example, Zmc is not a diagonal matrix. We note that Zmc is different in section 3 and in section 7.

#### 8) MODAL INDUCTANCE MATRIX AND MODAL CAPACITANCE MATRIX, FOR BIORTHONORMAL EIGENVECTORS

 $Lm := T^{T} \cdot L0 \cdot T \qquad Cm := T^{-1} \cdot C \cdot (T^{-1})^{T}$   $10^{9}Lm = \begin{pmatrix} 446.404 & 220.552 & 120.338 & 67.269 & 37.881 & 21.415 & 12.190 & 7.099 \\ 220.552 & 432.448 & 213.654 & 116.608 & 65.225 & 36.801 & 20.936 & 12.190 \\ 120.338 & 213.654 & 429.050 & 211.844 & 115.666 & 64.819 & 36.801 & 21.415 \\ 67.269 & 116.608 & 211.844 & 428.134 & 211.454 & 115.666 & 65.225 & 37.881 \\ 37.881 & 65.225 & 115.666 & 211.454 & 428.134 & 211.844 & 116.608 & 67.269 \\ 21.415 & 36.801 & 64.819 & 115.666 & 211.844 & 429.050 & 213.654 & 120.338 \\ 12.190 & 20.936 & 36.801 & 65.225 & 116.608 & 213.654 & 432.448 & 220.552 \\ 7.099 & 12.190 & 21.415 & 37.881 & 67.269 & 120.338 & 220.552 & 446.404 \end{pmatrix}$ 

nH/m

	93.415	-45.995	-2.952	-0.610	-0.141	-0.033	$-7.907 \times 10^{-3}$	-2.178×10 <sup>-3</sup>
10 <sup>12.</sup> Cm =	-45.995	118.313	-44.538	-2.653	-0.541	-0.124	-0.030	$-7.907 \times 10^{-3}$
	-2.952	-44.538	118.408	-44.519	-2.649	-0.540	-0.124	-0.033
	-0.610	-2.653	-44.519	118.412	-44.517	-2.649	-0.541	-0.141
	-0.141	-0.541	-2.649	-44.517	118.412	-44.519	-2.653	-0.610
	-0.033	-0.124	-0.540	-2.649	-44.519	118.408	-44.538	-2.952
	$-7.907 \times 10^{-3}$	-0.030	-0.124	-0.541	-2.653	-44.538	118.313	-45.995
	(-2.178×10 <sup>-3</sup>	$-7.907 \times 10^{-3}$	-0.033	-0.141	-0.610	-2.952	-45.995	93.415

pF/m

In this example, Lm and Cm are not diagonal matrices. We note that Lm and Cm are different in section 6 and in section 8.



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### Seminar 32

# Tutorial on Echo and Crosstalk in Printed Circuit Boards and Multi-Chip Modules — Lecture Slides

Part A — Propagation models

- 1. Introduction and definitions
- 2. The 2-conductor transmission line in the frequency domain
- 3. Problems involving a TL and linear terminations
- 4. Telegrapher's equations of a uniform MTL and modal decomposition
- 5. The characteristic impedance matrix
- 6. Biorthonormal eigenvectors and associated eigenvectors
- 7. The choice of eigenvectors and total decoupling
- 8. Propagation in the frequency domain
- 9. Matched termination circuit and pseudo-matched terminations
- 10. Problems involving an MTL and linear terminations

Part B — Techniques for reducing crosstalk and echo

- 11. The degradation of transmitted signals
- 12. Single-ended parallel links
- 13. Multichannel differential links
- 14. Modal signaling
- 15. Modal signaling in a degenerate interconnection
- 16. Pseudo-differential links

Appendix

Bibliography

Annexes

**Frédéric Broydé** received an M.S. degree in physics engineering and a Ph.D. in microwaves and microtechnologies. He is the chief technical officer of Excem and he directly takes part in engineering or R&D projects related to electromagnetic compatibility (EMC) and signal integrity. He is a Senior Member of the IEEE.

**Evelyne Clavelier** received the M.S. degree in physics engineering in 1984. She co-founded Excem in 1988. She is currently the chief executive officer of Excem, where she is also active as a senior R&D engineer. She is a Senior Member of the IEEE since 2002.

**Frédéric Broydé and Evelyne Clavelier** are authors or co-authors of more than 80 technical papers, and inventors or co-inventors for more than 50 patent families.

Excem 12, chemin des Hauts de Clairefontaine 78580 Maule - France

http://www.eurexcem.com

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